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RTL8214FCI-VC-CG

INTEGRATED QUAD 10/100/1000M ETHERNET TRANSCEIVER

DATASHEET

(CONFIDENTIAL: Development Partners Only)

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USING THIS DOCUMENT

This document is intended for the hardware and software engineer's general information on the Realtek RTL8214FCI-VC IC.

Though every effort has been made to ensure that this document is current and accurate, more information may have become available subsequent to the production of this guide.

ELECTROSTATIC DISCHARGE (ESD) WARNING

This product can be damaged by Electrostatic Discharge (ESD). When handling, care must be taken. Damage due to inappropriate handling is not covered by warranty.

Do not open the protective conductive packaging until you have read the following, and are at an approved anti-static workstation.

- Use an approved anti-static mat to cover your work surface
- Use a conductive wrist strap attached to a good earth ground
- Always discharge yourself by touching a grounded bare metal surface or approved anti-static mat before picking up an ESD-sensitive electronic component
- If working on a prototyping board, use a soldering iron or station that is marked as ESD-safe
- Always disconnect the microcontroller from the prototyping board when it is being worked on

REVISION HISTORY

Revision	Release Date	Summary
1.0	2014/11/13	First release.
1.1	2016/08/25	Revised Table 35 QSGMII Differential Transmitter Characteristics, page 43. Revised Table 36 QSGMII Differential Receiver Characteristics, page 44.
1.2	2018/08/29	Revised Table 6 Configuration Pins, page 11 (pin 85). Revised section 11.2 Mechanical Dimensions Notes, page 56. Corrected minor typing errors.
1.3	2021/09/03	Revised section 11 Mechanical Dimensions, page 56. Corrected minor typing errors.

Table of Contents

List of Tables

List of Figures

1. General Description

The RTL8214FCI-VC integrates quad independent 10/100/1000M Ethernet transceivers into a single IC, and performs all the physical layer (PHY) functions for 1000Base-T, 100Base-TX, and 10Base-T Ethernet on category 5 UTP cable except 1000Base-T half-duplex. 10Base-T functionality can also be achieved on standard category 3 or 4 cable.

This device includes PCS, PMA, and PMD sub-layers. They perform encoding/decoding, clock/data recovery, digital adaptive equalization, echo cancellers, crosstalk elimination, and line driver, as well as other required supporting circuit functions. The RTL8214FCI-VC also integrates an internal hybrid that allows the use of inexpensive 1:1 transformer modules.

Each of the four independent transceivers features an innovative RSGMII-Plus/QSGMII for reduced PCB traces. All transceivers can communicate with the MAC simultaneously through the same RSGMII-Plus/QSGMII.

2. Features

- Quad-port integrated 10/100/1000M Ethernet transceiver
- Each port supports full duplex in 10/100/1000M mode (half duplex is only supported in 10/100M mode)
- Supports RSGMII-Plus (5Gbps serial high speed interface) in 10/100/1000M mode
- Supports QSGMII (5Gbps serial high speed interface) in 10/100/1000M mode
- Physical interface supports 1000Base-X
- Physical interface supports 100Base-FX
- Supports IEEE 802.3az Energy Efficient Ethernet (EEE)
- Supports crossover detection and auto correction in 10Base-T/100Base-T
- Auto-detection and auto-correction of wiring pair swaps, pair skew, and pair polarity
- Auto-detection and auto-correction of wiring pair swaps, pair skew, and pair polarity
- Supports Realtek's Cable Test (RTCT)
- Supports Realtek's Green Ethernet
  - Link- On Cable Length Power Saving
  - Link-Down Power Saving
- Supports one interrupt output to external CPU for notification
- Low power consumption
- Easy layout, good EMI, and good thermal performance
- 25MHz crystal or 3.3V OSC input
- 3.3V and 1.1V power supply
- TQFP-176 E-PAD package

3. System Applications

3.1. High-Port-Density Gigabit Ethernet Switch; 1000Base-T/ 1000Base-X or 100Base-FX

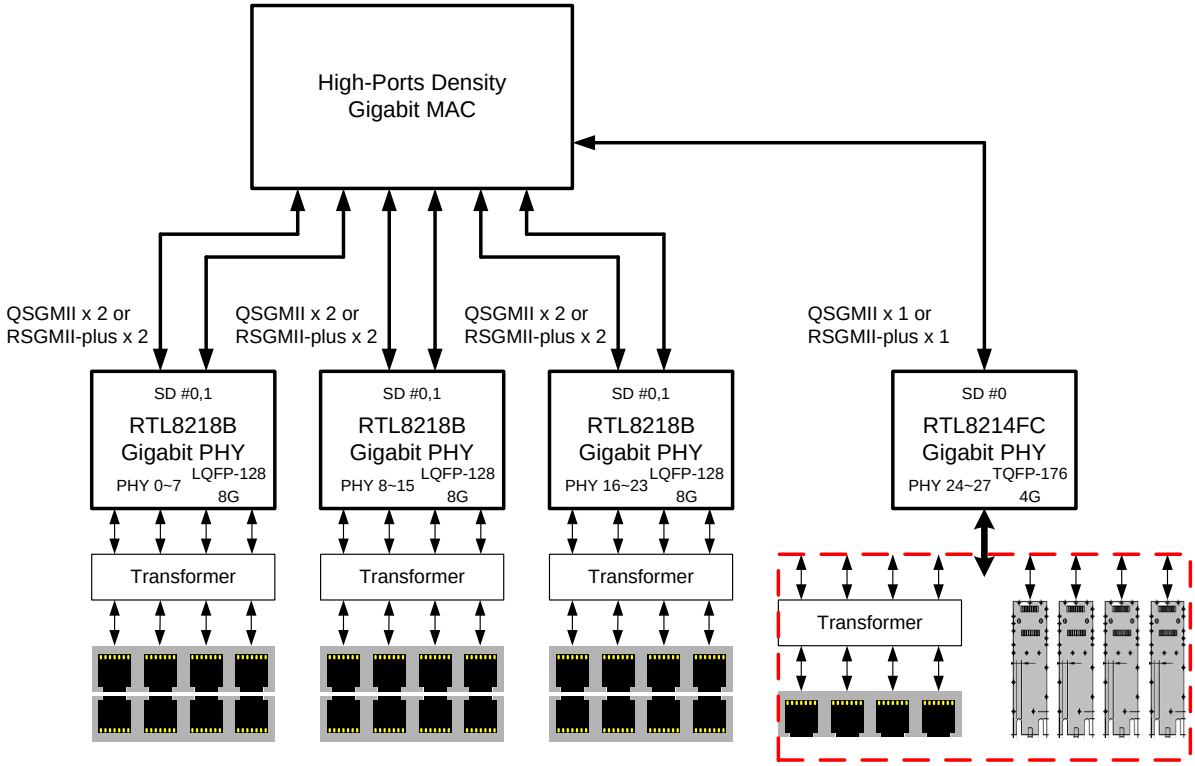


Figure 1. 24 + 4-Port Combo Gigabit Ethernet Switch (QSGMII or RSGMII-Plus Interface)

4. Block Diagram

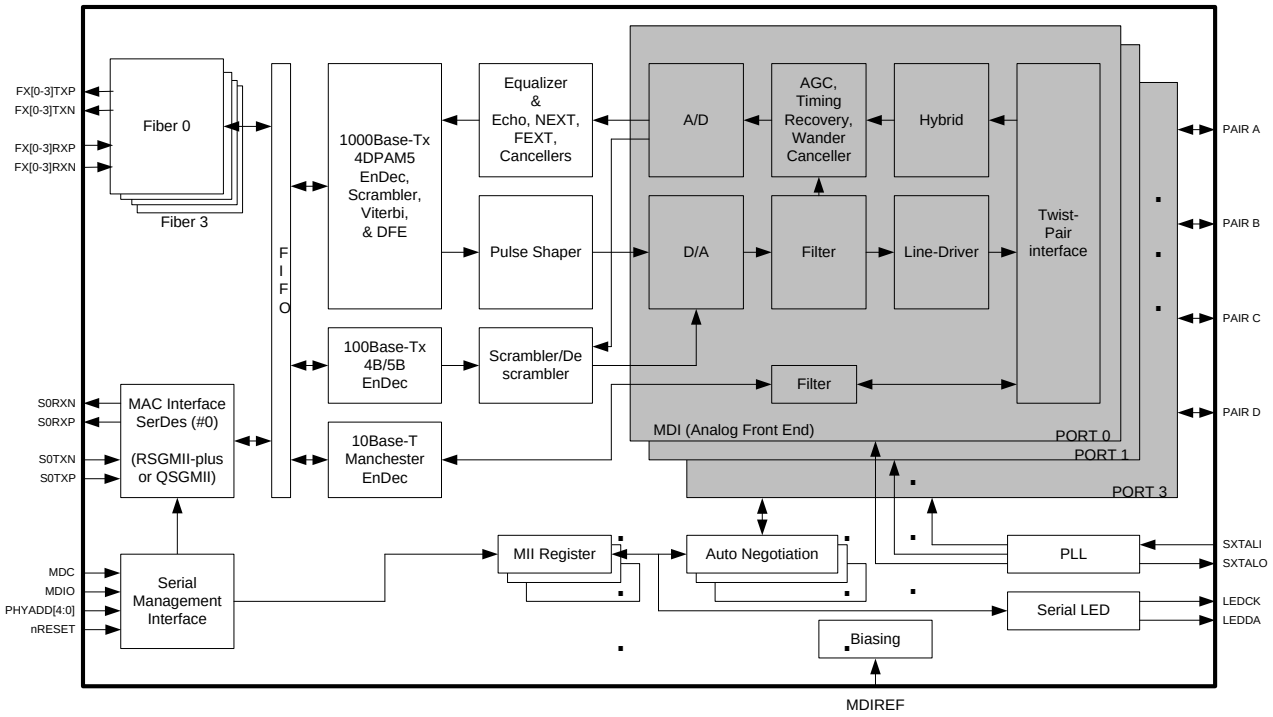


Figure 2. Block Diagram

5. Pin Assignments

5.1. Pin Assignments

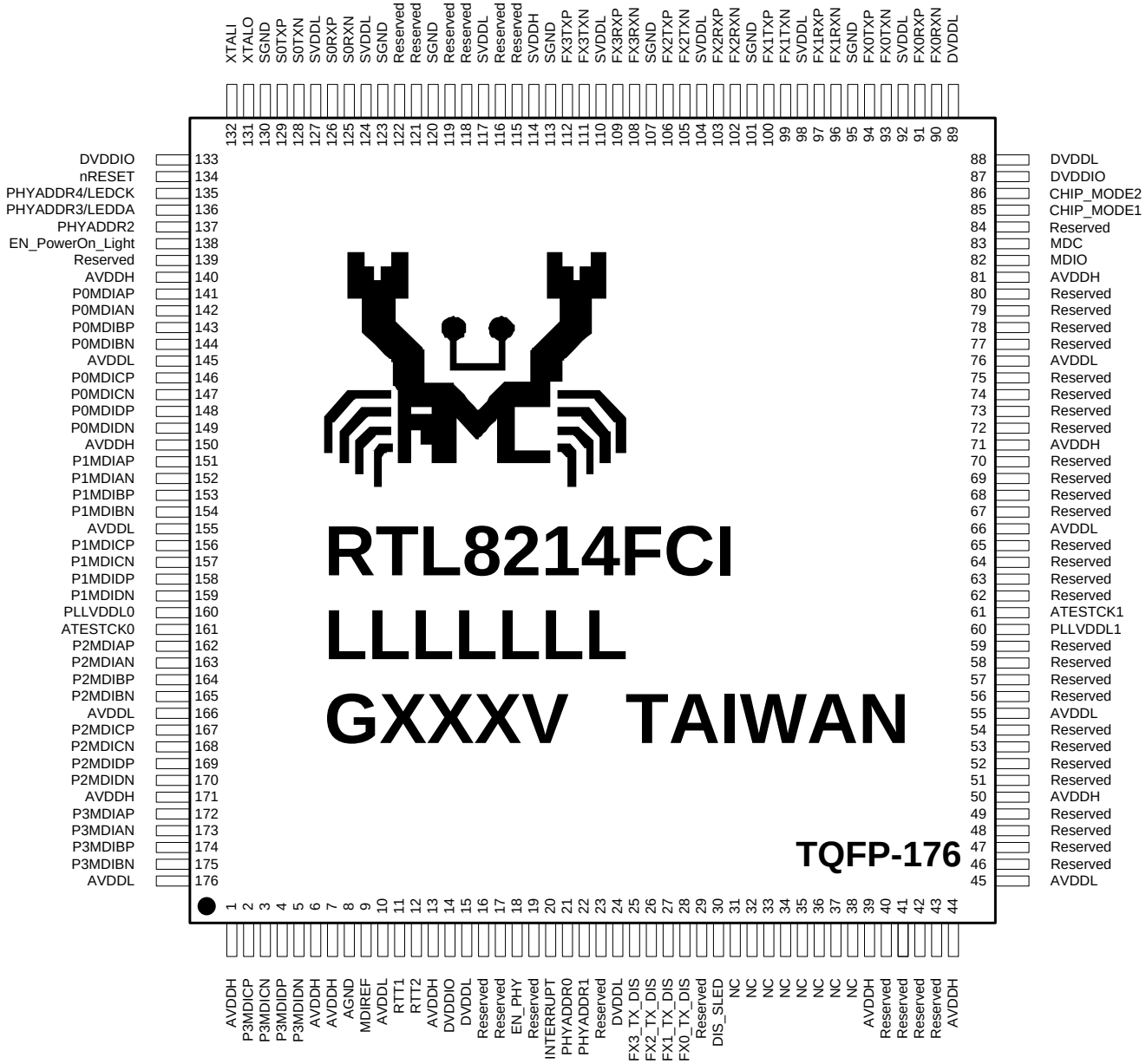


Figure 3. Pin Assignments

5.2. Package Identification

Green package is indicated by the 'G' in GXXXV (Figure 3). The version number is shown in the location marked 'V'.

5.3. Pin Assignment Tables

Upon Reset: Defined as a short time after the end of a hardware reset.

After Reset: Defined as the time after the specified 'Upon Reset' time.

I: Input Pin

O: Output Pin

I/O: Bi-Directional Input/Output Pin

P: Digital Power Pin

G: Digital Ground Pin

I_{PD}: Input Pin With Pull-Down Resistor

I_{PU}: Input Pin With Pull-Up Resistor; (Typical Value = 75K Ohm)

SP: SerDes Power Pin

I_S: Schmitt Trigger Input Pin

AI: Analog Input Pin

AO: Analog Output Pin

AI/O: Analog Bi-Directional Input/Output Pin

AP: Analog Power Pin

AG: Analog Ground Pin

A: Analog Pin

O_{PU}: Output Pin With Pull-Up Resistor; (Typical Value = 75K Ohm)

SG: SerDes Ground Pin

Table 1. Pin Assignment Table

Pin Name	Pin No.	Type
AVDDH	1	AP
P3MDICP	2	AI/O
P3MDICN	3	AI/O
P3MDIDP	4	AI/O
P3MDIDN	5	AI/O
AVDDH	6	AP
AVDDH	7	AP
AGND	8	AG
MDIREF	9	AO
AVDDL	10	AP
RTT1	11	AO
RTT2	12	AO
AVDDH	13	AP
DVDDIO	14	P
DVDDL	15	P
Reserved	16	I_{PU}
Reserved	17	I_{PU}
EN_PHY	18	I_{PU}
Reserved	19	I_{PU}

Pin Name	Pin No.	Type
INTERRUPT	20	I/O_{PU}
PHYADDR0	21	I_{PD}
PHYADDR1	22	I_{PD}
Reserved	23	I_{PD}
DVDDL	24	P
FX3_TX_DIS	25	I/O_{PU}
FX2_TX_DIS	26	I/O_{PU}
FX1_TX_DIS	27	I/O_{PU}
FX0_TX_DIS	28	I/O_{PU}
Reserved	29	I_{PU}
DIS_SLED	30	I_{PU}
NC	31	-
NC	32	-
NC	33	-
NC	34	-
NC	35	-
NC	36	-
NC	37	-
NC	38	-

Pin Name	Pin No.	Type
AVDDH	39	AP
Reserved	40	AI/O
Reserved	41	AI/O
Reserved	42	AI/O
Reserved	43	AI/O
AVDDH	44	AP
AVDDL	45	AP
Reserved	46	AI/O
Reserved	47	AI/O
Reserved	48	AI/O
Reserved	49	AI/O
AVDDH	50	AP
Reserved	51	AI/O
Reserved	52	AI/O
Reserved	53	AI/O
Reserved	54	AI/O
AVDDL	55	AP
Reserved	56	AI/O
Reserved	57	AI/O
Reserved	58	AI/O
Reserved	59	AI/O
PLLVDD1	60	AP
ATESTCK1	61	AO
Reserved	62	AI/O
Reserved	63	AI/O
Reserved	64	AI/O
Reserved	65	AI/O
AVDDL	66	AP
Reserved	67	AI/O
Reserved	68	AI/O
Reserved	69	AI/O
Reserved	70	AI/O
AVDDH	71	AP
Reserved	72	AI/O
Reserved	73	AI/O
Reserved	74	AI/O
Reserved	75	AI/O
AVDDL	76	AP
Reserved	77	AI/O
Reserved	78	AI/O
Reserved	79	AI/O
Reserved	80	AI/O
AVDDH	81	AP
MDIO	82	I/O

Pin Name	Pin No.	Type
MDC	83	I
Reserved	84	I_{PU}
CHIP_MODE1	85	I_{PU}
CHIP_MODE2	86	I_{PU}
DVDDIO	87	P
DVDDL	88	P
DVDDL	89	P
FX0RXN	90	AI
FX0RXP	91	AI
SVDDL	92	SP
FX0TXN	93	AO
FX0TXP	94	AO
SGND	95	SG
FX1RXN	96	AI
FX1RXP	97	AI
SVDDL	98	SP
FX1TXN	99	AO
FX1TXP	100	AO
SGND	101	SG
FX2RXN	102	AI
FX2RXP	103	AI
SVDDL	104	SP
FX2TXN	105	AO
FX2TXP	106	AO
SGND	107	SG
FX3RXN	108	AI
FX3RXP	109	AI
SVDDL	110	SP
FX3TXN	111	AO
FX3TXP	112	AO
SGND	113	SG
SVDDH	114	SP
Reserved	115	AO
Reserved	116	AO
SVDDL	117	SP
Reserved	118	AO
Reserved	119	AO
SGND	120	SP
Reserved	121	AI
Reserved	122	AI
SGND	123	SG
SVDDL	124	SP
S0RXN	125	AO
S0RXP	126	AO

Pin Name	Pin No.	Type
SVDDL	127	SP
S0TXN	128	AI
S0TXP	129	AI
SGND	130	SG
XTALO	131	AO
XTALI	132	AI
DVDDIO	133	P
nRESET	134	I_{PU}
PHYADDR4/LEDCK	135	I/O_{PD}
PHYADDR3/LEDDA	136	I/O_{PD}
PHYADDR2	137	I_{PD}
En_PowerOn_Light	138	I_{PU}
Reserved	139	I_{PU}
AVDDH	140	AP
P0MDIAP	141	AI/O
P0MDIAN	142	AI/O
P0MDIBP	143	AI/O
P0MDIBN	144	AI/O
AVDDL	145	AP
P0MDICP	146	AI/O
P0MDICN	147	AI/O
P0MDIDP	148	AI/O
P0MDIDN	149	AI/O
AVDDH	150	AP
P1MDIAP	151	AI/O
P1MDIAN	152	AI/O

Pin Name	Pin No.	Type
P1MDIBP	153	AI/O
P1MDIBN	154	AI/O
AVDDL	155	AP
P1MDICP	156	AI/O
P1MDICN	157	AI/O
P1MDIDP	158	AI/O
P1MDIDN	159	AI/O
PLLVDDL0	160	AP
ATESTCK0	161	AO
P2MDIAP	162	AI/O
P2MDIAN	163	AI/O
P2MDIBP	164	AI/O
P2MDIBN	165	AI/O
AVDDL	166	AP
P2MDICP	167	AI/O
P2MDICN	168	AI/O
P2MDIDP	169	AI/O
P2MDIDN	170	AI/O
AVDDH	171	AP
P3MDIAP	172	AI/O
P3MDIAN	173	AI/O
P3MDIBP	174	AI/O
P3MDIBN	175	AI/O
AVDDL	176	AP
GND	EPAD	G

6. Pin Descriptions

6.1. Media Dependent Interface Pins

Table 2. Media Dependent Interface Pins

Pin Name	Pin No.	Type	Description
P0MDIAP P0MDIAN P0MDIBP P0MDIBN P0MDICP P0MDICN P0MDIDP P0MDIDN	141 142 143 144 146 147 148 149	AI/O	Port 0 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100ohm termination resistor.
P1MDIAP P1MDIAN P1MDIBP P1MDIBN P1MDICP P1MDICN P1MDIDP P1MDIDN	151 152 153 154 156 157 158 159	AI/O	Port 1 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100ohm termination resistor.
P2MDIAP P2MDIAN P2MDIBP P2MDIBN P2MDICP P2MDICN P2MDIDP P2MDIDN	162 163 164 165 167 168 169 170	AI/O	Port 2 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100ohm termination resistor.
P3MDIAP P3MDIAN P3MDIBP P3MDIBN P3MDICP P3MDICN P3MDIDP P3MDIDN	172 173 174 175 2 3 4 5	AI/O	Port 3 Media Dependent Interface A~D. For 1000Base-T operation, differential data from the media is transmitted and received on all four pairs. For 100Base-TX and 10Base-T operation, only MDIAP/N and MDIBP/N are used. Auto MDIX can reverse the pairs MDIAP/N and MDIBP/N. Each of the differential pairs has an internal 100ohm termination resistor.

6.2. RSGMII-Plus Pins

Table 3. RSGMII-Plus Pins

Pin Name	Pin No.	Type	Description
S0RXP S0RXN	126 125	AO	RSGMII-Plus Differential Output. 5GHz serial interfaces to transfer data from an External device that supports the RSGMII-Plus interface. Differential pairs have an internal 100ohm termination resistor.
S0TXP S0TXN	129 128	AI	RSGMII-Plus Differential Input. 5GHz serial interfaces to receive data from an External device that supports the RSGMII-Plus interface. Differential pairs have an internal 100ohm termination resistor.

6.3. QSGMII Pins

Table 4. QSGMII Pins

Pin Name	Pin No.	Type	Description
S0RXP S0RXN	126 125	AO	QSGMII Differential Output. 5GHz serial interfaces to transfer data from an External device that supports the QSGMII interface. Differential pairs have an internal 100ohm termination resistor.
S0TXP S0TXN	129 128	AI	QSGMII Differential Input. 5GHz serial interfaces to receive data from an External device that supports the QSGMII interface. Differential pairs have an internal 100ohm termination resistor.

6.4. Serial LED Pins

Table 5. Parallel LED Pins

Pin Name	Pin No.	Type	Description
DIS_SLED	30	I_{PU}	Input Upon Reset, 1: Disable Serial LED function. 0: Enable Serial LED function
LEDCK	135	I/O_{PD}	Output after reset if Serial LED is enabled by DIS_SLED = 0. Used for Serial LED clock.
LEDDA	136	I/O_{PD}	Output after reset if Serial LED is enabled by DIS_SLED = 0. Used for Serial LED Data

6.5. Configuration Pins

Table 6. Configuration Pins

Pin Name	Pin No.	Type	Description
PHYADDR0	21	I_{PD}	PHYADDR0, PHY Address Select. These pins are the 5-bit IEEE-specified PHY address. The states of these five pins are latched during power-up or reset. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
PHYADDR1	22	I_{PD}	PHYADDR1, PHY Address Select. These pins are the 5-bit IEEE-specified PHY address. The states of these five pins are latched during power-up or reset. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
PHYADDR2	137	I_{PD}	PHYADDR2, PHY Address Select. These pins are the 5-bit IEEE-specified PHY address. The states of these five pins are latched during power-up or reset. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
PHYADDR3 / LEDDA	136	I/O_{PD}	PHYADDR3, PHY Address Select. These pins are the 5-bit IEEE-specified PHY address. The states of these five pins are latched during power-up or reset. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
PHYADDR4 / LEDCK	135	I/O_{PD}	PHYADDR4, PHY Address Select. These pins are the 5-bit IEEE-specified PHY address. The states of these five pins are latched during power-up or reset. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
EN_PHY	18	I_{PU}	Enable PHY Power 1: Power up all ports. 0: Power down all ports and set the MII register 0.11 power down as 1. *Note: This pin must be kept floating, or pulled high or low via an external 4.7k ohm resistor upon power on or reset.*
CHIP_MODE1	85	I_{PU}	CHIP_MODE[2:1]: 10: QSGMII 11: QSGMII 00: Reserved for Internal Use 01: Reserved for Internal Use *QSGMII with 4-port 10/100/1000Base-T (1000Base-X or 100Base-FX) by default. It can be configured as RSGMII-Plus via register.*
CHIP_MODE2	86	I_{PU}	Same as CHIP_MODE1
En_PowerOn_ Light	138	I_{PU}	En_PowerOn_Light. 1: Enable Serial LED Power On Light. 0: Disable Serial LED Power On Light *Note: This pin must be kept floating, and pulled high or low via an external 4.7k ohm resistor upon power on or reset.*

6.6. Miscellaneous Pins

Table 7. Miscellaneous Pins

Pin Name	Pin No.	Type	Description
MDC	83	I	MII Management Interface Clock Input. The clock reference for the MII management interface. The maximum frequency support is 8MHz.
MDIO	82	I/O	MII Management Interface Data Input/Output. MDIO transfer management data in and out of the device synchronous to the rising edge of MDC.
INTERRUPT	20	I/O_{PU}	Interrupt output when Interrupt even occurs. Active High by pull-down to GND via a 1K resister. Active Low by pull-up to DVDDIO via a 4.7K resister.
nRESET	134	I_{PU}	Hardware Reset (Active Low Reset Signal). To complete the reset function, this pin must be asserted for at least 10ms. It must be pulled high for normal operation.
MDIREF	9	AO	MDI Bias Resistor. Adjusts the reference current for all PHYs. This pin must connect to AGND via a 2.49k ohm resistor.
Reserved	40, 41, 42, 43, 46, 47, 48, 49, 51, 52, 53, 54, 56, 57, 58, 59, 62, 63, 64, 65, 67, 68, 69, 70, 72, 73, 74, 75, 77, 78, 79, 80,	AI/O	Reserved. Must be left floating in normal operation.
Reserved	121, 122,	AI	Reserved. Must be left floating in normal operation.
Reserved	118, 119,	AO	Reserved. Must be left floating in normal operation.
NC	31, 32, 33, 34, 35, 36, 37, 38,	-	We suggest NC pins are left floating.
XTALI	132	AI	25MHz Crystal Clock Input. 25MHz±50ppm tolerance crystal reference or oscillator input. When using a crystal, connect a loading capacitor from each pad to ground. When either using an oscillator or driving an external 25MHz clock from another device, XTALO should be kept floating. The maximum XTALI input voltage is 3.3V.
XTALO	131	AO	25MHz Crystal Clock Output. 25MHz±50ppm tolerance crystal output. Refer to XTALI.

6.7. Power and GND Pins

Table 8. Power and GND Pins

Pin Name	Pin No.	Type	Description
AVDDH	1, 6, 7, 13, 39, 44, 50, 71, 81, 140, 150, 171	AP	Analog High Voltage Power
AVDDL	10, 45, 55, 66, 76, 145, 155, 166, 176	AP	Analog Low Voltage Power
PLLVDD0	160	AP	PLL Power This pin should be filtered with a low resistance series ferrite bead and 1000pF + 2.2µF shunt capacitors to ground
PLLVDD1	60	AP	PLL Power This pin should be filtered with a low resistance series ferrite bead and 1000pF + 2.2µF shunt capacitors to ground
SVDDH	114	SP	QSGMII / RSGMII-Plus SerDes High Voltage Power
SVDDL	92, 98, 104, 110, 117, 124, 127	SP	QSGMII / RSGMII-Plus SerDes Low Voltage Power
DVDDIO	14, 87, 133	P	Digital I/O Power
DVDDL	15, 24, 88, 89	P	Digital Low Voltage Power
AGND	8	AG	Analog Ground
SGND	95, 101, 107, 113, 120, 123, 130	SG	QSGMII / RSGMII-Plus SerDes Ground
GND	EPAD	G	Ground

6.8. Test Pins

Table 9. Test Pins

Pin Name	Pin No.	Type	Description
RTT1	11	AO	Reserved for Internal Use. Can be Left Floating or tied to GND via a 1K resister.
RTT2	12	AO	Reserved for Internal Use. Can be Left Floating or tied to GND via a 1K resister.
ATESTCK0	161	AO	Reserved for Internal Use. Can be Left Floating or tied to GND via a 1K resister.
ATESTCK1	61	AO	Reserved for Internal Use. Can be Left Floating or tied to GND via a 1K resister.
Reserved	17	I_{PU}	Reserved for Internal Use. Must be Left Floating or pulled-up to DVDDIO by 4.7K resister
Reserved	16	I_{PU}	Reserved for Internal Use. Must be Left Floating or pulled-up to DVDDIO by 4.7K resister
Reserved	19	I_{PU}	Reserved for internal used Should be pull-down via a 1K resister to GND for normal operation. This pin should be tied to ground for normal operation
Reserved	23	I_{PU}	Reserved for Internal Use. Must be Left Floating or pulled-up to DVDDIO by 4.7K resister
Reserved	29	I_{PU}	Reserved for internal used This pin should be tied to GND via a 1K resister for normal operation
Reserved	84	I_{PU}	Reserved for internal use. Must be tied to GND via a 1K resister for normal operation
Reserved	115	AO	Reserved for Internal Use. Must be Left Floating.
Reserved	116	AO	Reserved for Internal Use. Must be Left Floating.
Reserved	139	I_{PU}	Reserved for Internal Use. Must be pulled-down to ground by 1K resister for normal operation

6.9. 1000Base-X/100Base-FX Interface Pins

Table 10. 1000Base-X/100Base-FX Interface Pins

Pin Name	Pin No.	Type	Description
FX0RXP FX0RXN	91 90	AI	Port 0 1000Base-X Receiver Pair (1.25GHz Differential Signal Input). Port 0 100Base-FX Receiver Pair (125MHz Differential Signal Input).
FX0TXP FX0TXN	94 93	AO	Port 0 1000Base-X Transmit Pair (1.25GHz Differential Signal Output). Port 0 100Base-FX Transmit Pair (125MHz Differential Signal Output).
FX1RXP FX1RXN	97 96	AI	Port 1 1000Base-X Receiver Pair (1.25GHz Differential Signal Input). Port 1 100Base-FX Receiver Pair (125MHz Differential Signal Input).
FX1TXP FX1TXN	100 99	AO	Port 1 1000Base-X Transmit Pair (1.25GHz Differential Signal Output). Port 1 100Base-FX Transmit Pair (125MHz Differential Signal Output).
FX2RXP FX2RXN	103 102	AI	Port 2 1000Base-X Receiver Pair (1.25GHz Differential Signal Input). Port 2 100Base-FX Receiver Pair (125MHz Differential Signal Input).
FX2TXP FX2TXN	106 105	AO	Port 2 1000Base-X Transmit Pair (1.25GHz Differential Signal Output). Port 2 100Base-FX Transmit Pair (125MHz Differential Signal Output).
FX3RXP FX3RXN	109 108	AI	Port 3 1000Base-X Receiver Pair (1.25GHz Differential Signal Input). Port 3 100Base-FX Receiver Pair (125MHz Differential Signal Input).
FX3TXP FX3TXN	112 111	AO	Port 3 1000Base-X Transmit Pair (1.25GHz Differential Signal Output). Port 3 100Base-FX Transmit Pair (125MHz Differential Signal Output).
FX0_TX_DIS / GPIO3	28	I/O_{PU}	Port 0 100BaseFX / 1000Base-X Transmit Optical module Power Control
FX1_TX_DIS / GPIO2	27	I/O_{PU}	Port 1 100BaseFX / 1000Base-X Transmit Optical module Power Control
FX2_TX_DIS / GPIO 1	26	I/O_{PU}	Port 2 100BaseFX / 1000Base-X Transmit Optical module Power Control
FX3_TX_DIS / GPIO 0	25	I/O_{PU}	Port 3 100BaseFX / 1000Base-X Transmit Optical module Power Control

7. Function Description

7.1. MDI Interface

The RTL8214FCI-VC embeds four 10/100/1000M Ethernet PHYs in one chip. Each port uses a single common MDI interface to support 1000Base-T, 100Base-TX, and 10Base-T. This interface consists of four signal pairs-A, B, C, and D. Each signal pair consists of two bi-directional pins that can transmit and receive at the same time. The MDI interface has internal termination resistors, and therefore reduces BOM cost and PCB complexity. For 1000Base-T, all four pairs are used in both directions at the same time. For 10/100M links and during auto-negotiation, only pairs A and B are used.

7.2. 1000Base-T Transmit Function

The 1000Base-T transmit function performs 8B/10B coding, scrambling, 4D-PAM5 encoding. These code groups are passed through a waveform-shaping filter to minimize EMI effect, and are transmitted onto the 4-pair CAT5 cable at 125MBaud/s through a D/A converter.

7.3. 1000Base-T Receive Function

Input signals from the media pass through the sophisticated on-chip hybrid circuit to subtract the transmitted signal from the input signal for effective reduction of near-end echo. The received signal is processed with state-of-the-art technology, e.g., adaptive equalization, BLW (Baseline Wander) correction, cross-talk cancellation, echo cancellation, timing recovery, error correction, and 4D-PAM5 decoding. The 8-bit-wide data is recovered and is sent to the GMII interface at a clock speed of 125MHz. The Rx MAC retrieves the packet data from the internal receive MII/GMII interface and sends it to the packet buffer manager.

7.4. 100Base-TX Transmit Function

The 100Base-TX transmit function performs parallel to serial conversion, 4B/5B coding, scrambling, NRZ/NRZI conversion, and MLT-3 encoding. The 5-bit serial data stream after 4B/5B coding is then scrambled as defined by the TP-PMD Stream Cipher function to flatten the power spectrum energy such that EMI effects can be reduced significantly.

The scrambled seed is based on PHY addresses and is unique for each port. After scrambling, the bit stream is driven into the network media in the form of MLT-3 signaling. The MLT-3 multi-level signaling technology moves the power spectrum energy from high frequency to low frequency, which also reduces EMI emissions.

7.5. 100Base-TX Receive Function

The receive path includes a receiver composed of an adaptive equalizer and DC restoration circuits (to compensate for an incoming distorted MLT-3 signal), an MLT-3 to NRZI and NRZI to NRZ converter to convert analog signals to digital bit-stream, and a PLL circuit to clock data bits with minimum bit error rate. A de-scrambler, 5B/4B decoder, and serial-to-parallel conversion circuits are followed by the PLL circuit. Finally, the converted parallel data is fed into the MAC.

7.6. 10Base-T Transmit Function

The output 10Base-T waveform is Manchester-encoded before it is driven onto the network media. The internal filter shapes the driven signals to reduce EMI emissions, eliminating the need for an external filter.

7.7. 10Base-T Receive Function

The Manchester decoder converts the incoming serial stream to NRZ data when the squelch circuit detects the signal level is above squelch level.

7.8. Auto-Negotiation for UTP

The RTL8214FCI-VC obtains the states of duplex, speed, and flow control ability for each port in UTP mode through the auto-negotiation mechanism defined in the IEEE 802.3 specifications. During auto-negotiation, each port advertises its ability to its link partner and compares its ability with advertisements received from its link partner. By default, the RTL8214FCI-VC advertises full capabilities (1000full, 100full, 100half, 10full, 10half) together with flow control ability.

7.9. Crossover Detection and Auto Correction

The RTL8214FCI-VC automatically determines whether it needs to crossover between pairs, so that an external crossover cable is not required. When connecting to a device that does not perform MDI crossover, the RTL8214FCI-VC automatically switches its pin pairs to communicate with the remote device. When connecting to a device that does have MDI crossover capability, an algorithm determines which end performs the crossover function.

The crossover detection and auto correction function can be disabled via register configuration. The RTL8214FCI-VC is set to MDI Crossover by default. The pin mapping in MDI and MDI Crossover mode is given below.

Table 11. Media Dependent Interface Pin Mapping

Pairs	MDI			MDI Crossover		
	1000Base-T	100Base-TX	10Base-T	1000Base-T	100Base-TX	10Base-T
A	A	TX	TX	B	RX	RX
B	B	RX	RX	A	TX	TX
C	C	Unused	Unused	D	Unused	Unused
D	D	Unused	Unused	C	Unused	Unused

7.10. Polarity Correction

The RTL8214FCI-VC automatically corrects polarity errors on the receiver pairs in 1000Base-T and 10Base-T modes. In 100Base-TX mode, the polarity is irrelevant.

In 1000Base-T mode, receive polarity errors are automatically corrected based on the sequence of idle symbols. Once the descrambler is locked, the polarity is also locked on all pairs. The polarity becomes unlocked only when the receiver loses lock.

In 10Base-T mode, polarity errors are corrected based on the detection of valid spaced link pulses. The detection begins during the MDI crossover detection phase and locks when 10Base-T links up. The polarity becomes unlocked when the link is down.

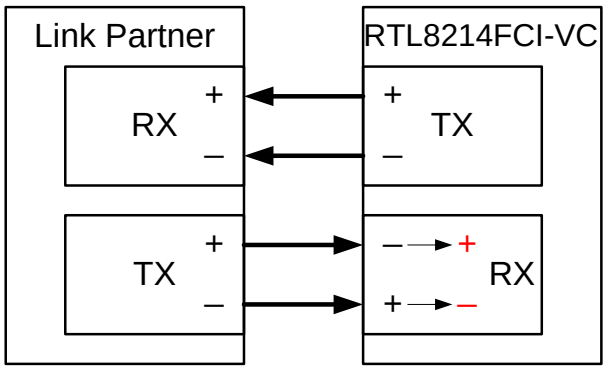


Figure 4. Conceptual Example of Polarity Correction

7.11. MDC/MDIO Interface

The RTL8214FCI-VC supports the IEEE compliant Management Data Input/Output (MDIO) Interface. This is the only method for the MAC to acquire the status of the PHY. The Media Independent Interface Management (MIIM) registers are written and read serially, using the MDC/MDIO pins. Data transferred to and from the MDIO pins is synchronized with the MDC clock. All transfers are initiated by the MAC. A clock of up to 8MHz must drive the MDC pin of the RTL8214FCI-VC.

The MII register is a block of 32 registers, each 16 bits wide. Certain registers are defined by IEEE 802.3 and are required for compliance (0~10, 15).

The MDIO frame structure starts with a 32-bit preamble, which is required by the RTL8214FCI-VC. The following data includes a start-of-frame marker, an op-code, a 10-bit address field, and a 16-bit data field. The address field is divided into two 5-bit segments. The first segment identifies the PHY address and the second identifies the register being accessed.

The 5-bits of the PHY address are determined by the hardware strapping values during power up. The MDIO protocol provides both read and write operations. During a write operation, the MAC drives the MDIO line for the entire frame. For a read operation, a turn-around time is inserted in the frame to allow the PHY to drive back to the MAC. The MDIO pin of the MAC must be put in high-impedance during these bit times. Figure 5 and Figure 6 depict the MDIO read and write frame format respectively.

The RTL8214FCI-VC is permanently programmed for preamble suppression. A preamble of 32 ‘1’ bits is required only for the first read or write. The management preamble may be as short as 1 bit.

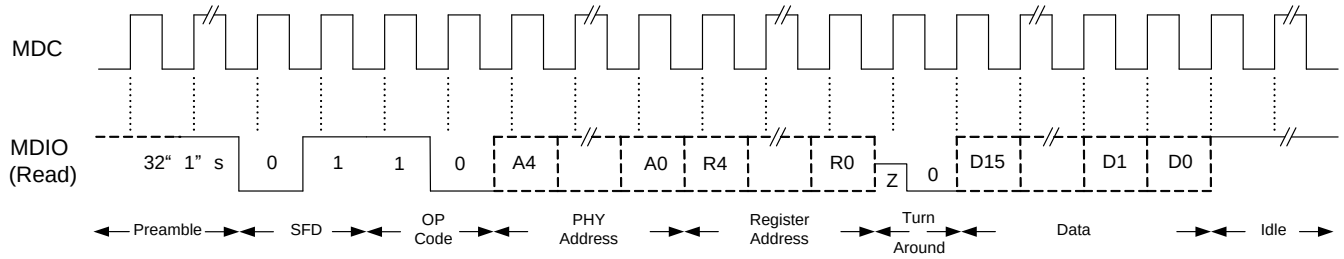


Figure 5. MDIO Read Frame Format

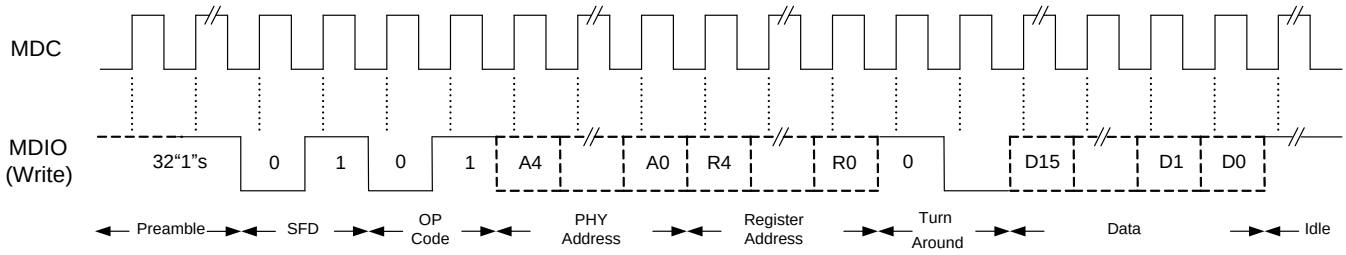


Figure 6. MDIO Write Frame Format

7.12. Reduced Serial Gigabit Media Independent Interface Plus (RSGMII-Plus)

RSGMII-Plus (Reduced Serial Gigabit Media Independent Interface plus) reduces PCB complexity and IC pin count. This innovative 5Gbps serial interface provides an up to 10 inch MAC to PHY communication path. RSGMII-Plus can carry the full duplex gigabit Ethernet data streams of four ports simultaneously, using only 4 pins.

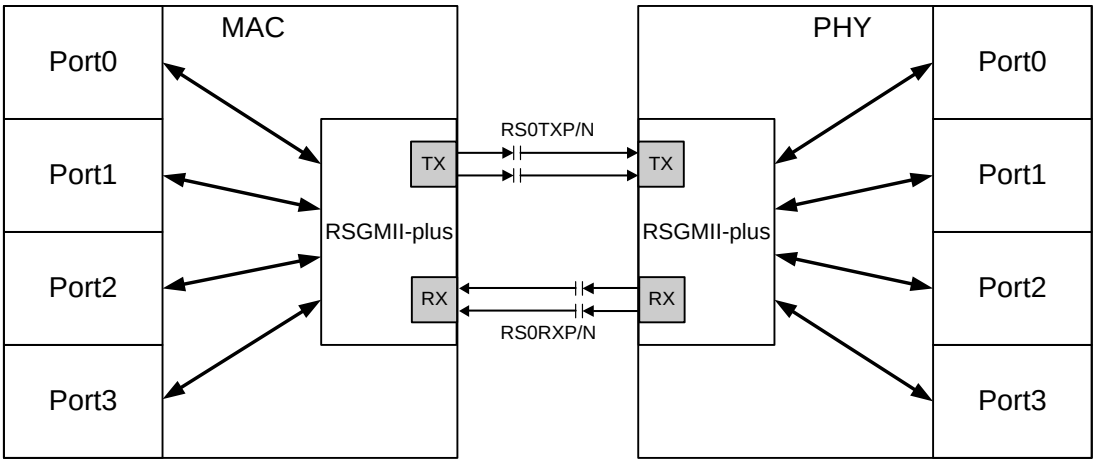


Figure 7. RSGMII-Plus Interconnection Diagram

7.13. Quad Serial Gigabit Media Independent Interface (QSGMII)

QSGMII (Quad Serial Gigabit Media Independent Interface) reduces PCB complexity and IC pin count. This innovative 5Gbps serial interface provides an up to 5 inch MAC to PHY communication path. QSGMII can carry the full duplex gigabit Ethernet data streams of four ports simultaneously, using only 4 pins.

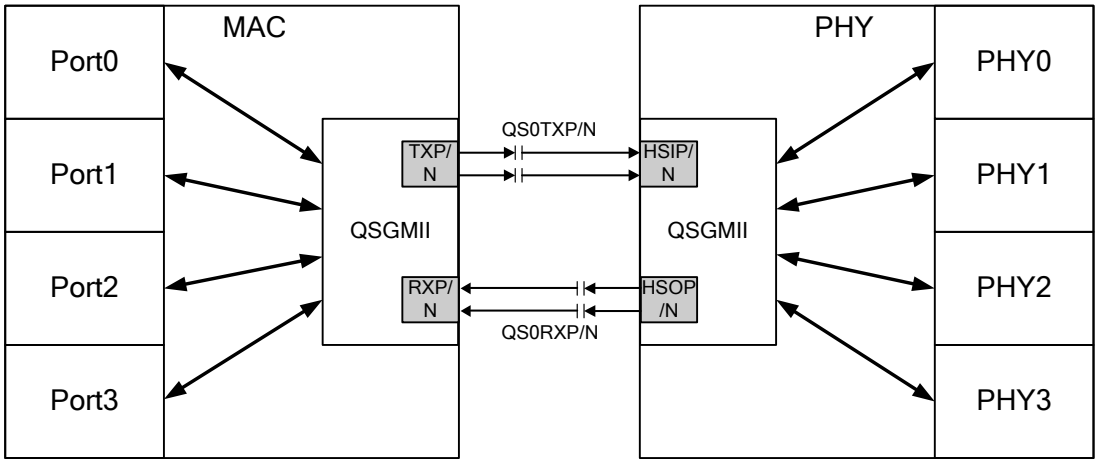


Figure 8. QSGMII Interconnection Diagram

7.13.1. RSGMII-Plus Interface

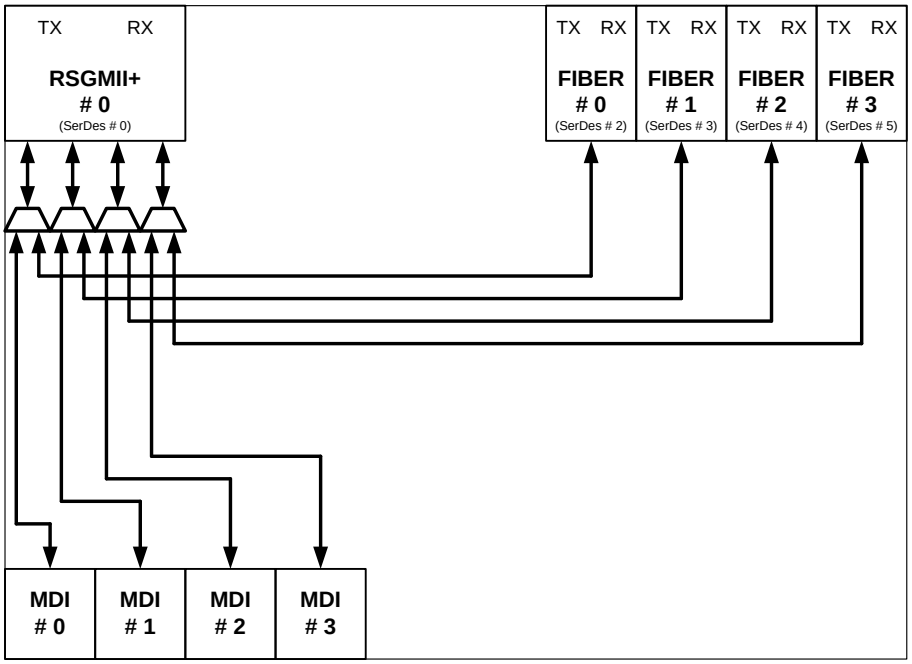


Figure 9. [MDI x 4] + [RSGMII-Plus x 1] + [1000Base-X/100Base-FX x 4]

7.13.2. QSGMII Interface

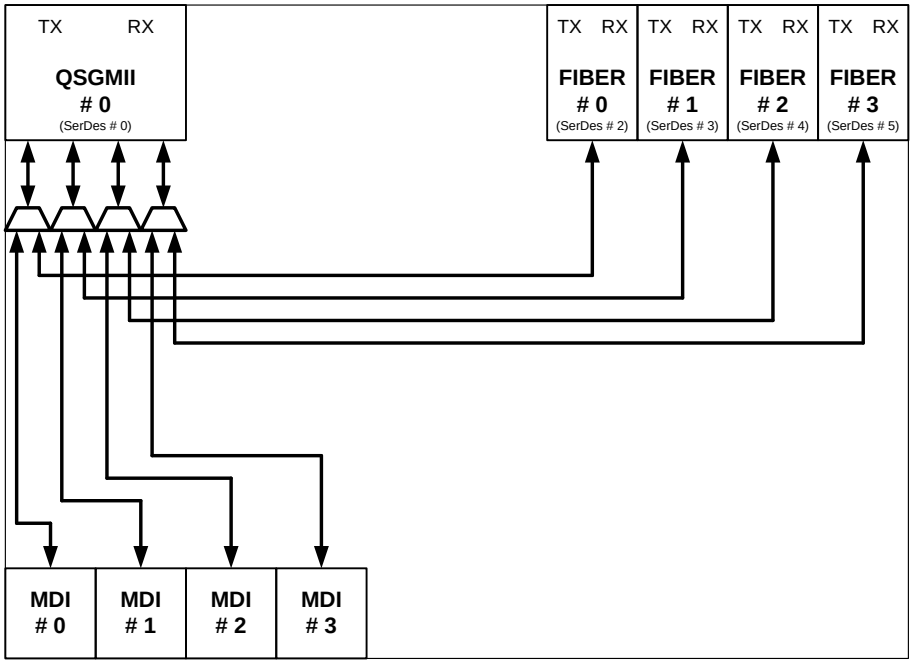


Figure 10. [MDI x 4] + [QSGMII x 1] + [1000Base-X/100Base-FX x 4]

7.14. Fiber Interface

7.14.1. Auto Sensing

The RTL8214FCI-VC supports the SerDes interface. The interface can be used in 1000Base-X/100Base-FX interface applications. The RTL8214FCI-VC can automatically detect and select between 1000Base-X and 100Base-FX modes.

7.14.2. FX_TX_DIS

The RTL8214FCI-VC supports the FX_TX_DIS to turn off the Fiber Optical transmitter

7.14.3. Fiber Interface Application Circuit

In interconnection, the chip side uses the OEnTXP/N pair to transmit 1.25G/125M data to the fiber side with 0.1uF AC couple. In the same time, chip side use OEnRXP/N pair to receive 1.25G/125M data from fiber side with 0.1µF AC couple.

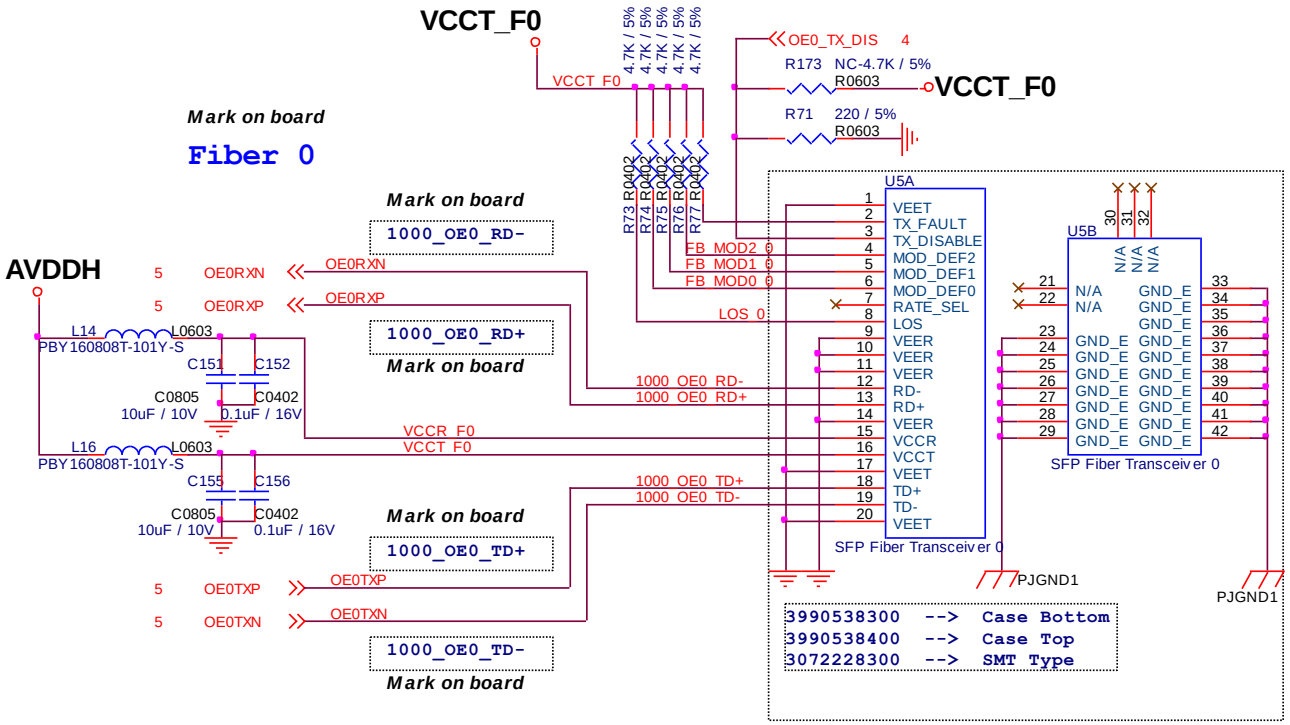


Figure 11. Fiber Interface Application Circuit

7.15. Serial LED

7.15.1. Port Status Indicator

The RTL8214FCI-VC supports serial LED mode. In the serial LED mode, the data is clocked through a shift register and the shifted symbols are output to the 36 LED pins. Each MDI port has three indicator symbols and each fiber port has three indicator symbols. Each symbol may have different indicator information

7.15.2. LED Configuration

Table 12. Serial LED Per-LED Control

PHY0, Reg.30: 8, Reg.=31=0x281

Reg.bit	Name	Mode	Description	Default
18.[15:12]	LED_00_Mode	RW	Assign LEDn to Port. 0000: MDI0 0001: MDI1 0010: MDI2 0011: MDI3 0100: Reserved 0101: Reserved 0110: Reserved 0111: Reserved 1000: FX0 1001: FX1 1010: FX2 1011: FX3 1100~1110: Reserved 1111: Disable	0x0
18.11		RW	1000M Speed Indicator.	0x0
18.10		RW	100M Speed Indicator.	0x0
18.9		RW	10M Speed Indicator.	0x0
18.8		RW	Reserved	0x0
18.7		RW	1000M Activity Indicator. Act blinking when the corresponding port is transmitting or receiving.	0x0
18.6		RW	100M Activity Indicator. Act blinking when the corresponding port is transmitting or receiving.	0x0
18.5		RW	10M Activity Indicator. Act blinking when the corresponding port is transmitting or receiving.	0x0
18.4		RW	Reserved	0x0
18.3		RW	Duplex Indicator.	0x0
18.2		RW	Collision Indicator. Blinking when a collision occurs.	0x0
18.1		RW	Tx Activity Indicator. Blinking when the corresponding port is transmitting.	0x0
18.0		RW	Rx Activity Indicator. Blinking when the corresponding port is receiving.	0x0
19[15:0]	LED_01_Mode	RW	Same as LED_00_Mode	-
20[15:0]	LED_02_Mode	RW	Same as LED_00_Mode	-

Reg.bit	Name	Mode	Description	Default
21[15:0]	LED_03_Mode	RW	Same as LED_00_Mode	-
22[15:0]	LED_04_Mode	RW	Same as LED_00_Mode	-
23[15:0]	LED_05_Mode	RW	Same as LED_00_Mode	-

PHY0, Reg.29 = 8, Reg.=31=0x282

Reg.bit	Name	Mode	Description	Default
16[15:0]	LED_06_Mode	RW	Same as LED_00_Mode	-
17[15:0]	LED_07_Mode	RW	Same as LED_00_Mode	-
18[15:0]	LED_08_Mode	RW	Same as LED_00_Mode	-
19[15:0]	LED_09_Mode	RW	Same as LED_00_Mode	-
20[15:0]	LED_10_Mode	RW	Same as LED_00_Mode	-
21[15:0]	LED_11_Mode	RW	Same as LED_00_Mode	-
22[15:0]	LED_12_Mode	RW	Same as LED_00_Mode	-
23[15:0]	LED_13_Mode	RW	Same as LED_00_Mode	-

PHY0, Reg.29 = 8, Reg.=31=0x283

Reg.bit	Name	Mode	Description	Default
16[15:0]	LED_14_Mode	RW	Same as LED_00_Mode	-
17[15:0]	LED_15_Mode	RW	Same as LED_00_Mode	-
18[15:0]	LED_16_Mode	RW	Same as LED_00_Mode	-
19[15:0]	LED_17_Mode	RW	Same as LED_00_Mode	-
20[15:0]	LED_18_Mode	RW	Same as LED_00_Mode	-
21[15:0]	LED_19_Mode	RW	Same as LED_00_Mode	-
22[15:0]	LED_20_Mode	RW	Same as LED_00_Mode	-
23[15:0]	LED_21_Mode	RW	Same as LED_00_Mode	-

PHY0, Reg.29 = 8, Reg.=31=0x284

Reg.bit	Name	Mode	Description	Default
16[15:0]	LED_22_Mode	RW	Same as LED_00_Mode	-
17[15:0]	LED_23_Mode	RW	Same as LED_00_Mode	-
18[15:0]	LED_24_Mode	RW	Same as LED_00_Mode	-
19[15:0]	LED_25_Mode	RW	Same as LED_00_Mode	-
20[15:0]	LED_26_Mode	RW	Same as LED_00_Mode	-
21[15:0]	LED_27_Mode	RW	Same as LED_00_Mode	-
22[15:0]	LED_28_Mode	RW	Same as LED_00_Mode	-
23[15:0]	LED_29_Mode	RW	Same as LED_00_Mode	-

PHY0, Reg.29 = 8, Reg.=31=0x285

Reg.bit	Name	Mode	Description	Default
16[15:0]	LED_30_Mode	RW	Same as LED_00_Mode	-
17[15:0]	LED_31_Mode	RW	Same as LED_00_Mode	-
18[15:0]	LED_32_Mode	RW	Same as LED_00_Mode	-
19[15:0]	LED_33_Mode	RW	Same as LED_00_Mode	-
20[15:0]	LED_34_Mode	RW	Same as LED_00_Mode	-
21[15:0]	LED_35_Mode	RW	Same as LED_00_Mode	-

Table 13. Serial LED Mode Configuration (Per-Port 3 LEDs)

of Per-LED Register	LED_MODE [1:0]=11	LED_MODE [1:0]=10	LED_MODE [1:0]=01	LED_MODE [1:0]=00
LED35	0x0FF0	0x0880	0x0880	0x0FF0
LED34	0x1FF0	0x1880	0x1880	0x1FF0
LED33	0x2FF0	0x2880	0x2880	0x2FF0
LED32	0x3FF0	0x3880	0x3880	0x3FF0
LED31	0x0800	0x0440	0x0660	0x8CC0
LED30	0x1800	0x1440	0x1660	0x9CC0
LED29	0x2800	0x2440	0x2660	0xACC0
LED28	0x3800	0x3440	0x3660	0xBCC0
LED27	0x0400	0x0220	0x8880	0xF000
LED26	0x1400	0x1220	0x9880	0xF000
LED25	0x2400	0x2220	0xA880	0xF000
LED24	0x3400	0x3220	0xB880	0xF000
LED23	0x8CC0	0x8880	0x8440	0xF000
LED22	0x9CC0	0x9880	0x9440	0xF000
LED21	0xACC0	0xA880	0xA440	0xF000
LED20	0xBCC0	0xB880	0xB440	0xF000
LED19	0x8800	0x8440	0xF000	0xF000
LED18	0x9800	0x9440	0xF000	0xF000
LED17	0xA800	0xA440	0xF000	0xF000
LED16	0xB800	0xB440	0xF000	0xF000
LED15	0x8400	0xF000	0xF000	0xF000
LED14	0x9400	0xF000	0xF000	0xF000
LED13	0xA400	0xF000	0xF000	0xF000
LED12	0xB400	0xF000	0xF000	0xF000
LED11	0xF000	0xF000	0xF000	0xF000
LED10	0xF000	0xF000	0xF000	0xF000
LED09	0xF000	0xF000	0xF000	0xF000
LED08	0xF000	0xF000	0xF000	0xF000
LED07	0xF000	0xF000	0xF000	0xF000
LED06	0xF000	0xF000	0xF000	0xF000
LED05	0xF000	0xF000	0xF000	0xF000
LED04	0xF000	0xF000	0xF000	0xF000
LED03	0xF000	0xF000	0xF000	0xF000

of Per-LED Register	LED_MODE [1:0]=11	LED_MODE [1:0]=10	LED_MODE [1:0]=01	LED_MODE [1:0]=00
LED02	0xF000	0xF000	0xF000	0xF000
LED01	0xF000	0xF000	0xF000	0xF000
LED00	0xF000	0xF000	0xF000	0xF000

Notes:
LED_MODE [1:0]=11
MDI: [Link/Act] [SPD1000] [SPD100]
FX: [Link/Act] [SPD1000] [SPD100]

LED_MODE [1:0]=10
MDI: [SPD1000/Act] [SPD100/Act] [SPD10/Act]
FX: [SPD1000/Act] [SPD100/Act] [Disable]

LED_MODE [1:0]=01
MDI: [SPD1000/Act] [SPD100(10)/Act]
FX: [SPD1000/Act] [SPD100/Act]

LED_MODE [1:0]=00
MDI: [Link/Act]
FX: [Link/Act]

7.15.3. Serial LED Configuration Register

Table 14. Serial LED Per-LED Control

PHY0, Reg.29 = 8, Reg.=31=0x280

Reg.bit	Name	Mode	Description	Default
16[15:14]	Reserved	RW	Reserved	00
16[13:12]	cfg_led_mode	RW	00: LED_Mode0. Per-Port 2 LEDs 01: LED_Mode1. Per-Port 2 LEDs 10: LED_Mode2. Per-Port 3 LEDs 11: LED_Mode3. Per-Port 3 LEDs	11
16[11]	Reserved	RW	Reserved	0
16[10:8]	Serial Blink Rate	RW	LED Blink Rate Configuration. 000: 32ms 001: 64ms 010: 128ms 011: 256ms 100: 512ms 101: 1024ms 110: 48ms 111: 96ms	000
16[7:6]	serial led burst cycle	RW	2'b00: 8 (ms) 2'b01: 16 2'b10: 32 2'b11: 64	10

Reg.bit	Name	Mode	Description	Default
16[5:4]	serial led clock cycle	RW	2'b00: 32 (ns) 2'b01: 64 2'b10: 96 2'b11: 192	11
16[3]	led_seri_active_low	RW	Serial LED active LOW 0: LED status active high 1: LED status active low	1
16[2]	led_seri_disable	RW	Disable Serial LED. 1: Disable 0: Enable Default by strapping option (pin-30)	
16[1]	led_data_e_b	RW	Serial LED DATA_EN	
16[0]	led_clk_e_b	RW	Serial LED CLK_EN	

Note: Upon reset, the RTL8214FCI-VC supports chip diagnostics and LED functions by blinking all LEDs once via the LED_PowerOn_Light strapping pin configuration.

7.15.4. Serial LED Timing Definitions

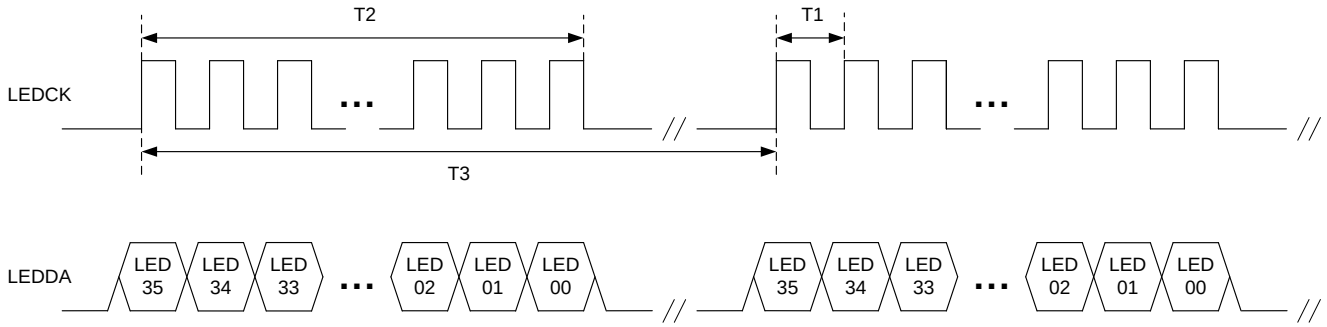


Figure 12. Serial LED Timing Definitions

7.16. Realtek Cable Test (RTCT)

The RTL8214FCI-VC physical layer transceivers use DSP technology to implement the Realtek Cable Test (RTCT) feature. The RTCT function can be used to detect short, open, or impedance mismatch in each differential pair.

7.17. Green Ethernet

7.17.1. Link-Up and Cable Length Power Saving

The RTL8214FCI-VC provides link-up and dynamic detection of cable length and dynamic adjustment of power required for the detected cable length. This feature provides high performance with minimum power consumption.

7.17.2. Link-Down Power Saving

The RTL8214FCI-VC implements link-down power saving on a per-port basis, greatly cutting power consumption when the network cable is disconnected. After it detects an incoming signal, it wakes up from link-down power saving and operates in normal mode.

7.18. IEEE 802.3az Energy Efficient Ethernet (EEE)

The RTL8214FCI-VC supports IEEE 802.3az Energy Efficient Ethernet ability for 1000Base-T and 100Base-TX in full duplex operation.

The Energy Efficient Ethernet (EEE) optional operational mode combines the IEEE 802.3 Media Access Control (MAC) sub-layer with 100Base-T and 1000Base-T Physical Layers defined to support operation in Low Power Idle mode. When Low Power Idle mode is enabled, systems on both sides of the link can disable portions of the functionality and save power during periods of low link utilization.

- For 1000Base-T: Supports Energy Efficient Ethernet with the optional function of Low Power Idle
- For 100Base-TX: Supports Energy Efficient Ethernet with the optional function of Low Power Idle

7.19. Interrupt Pin for External CPU

The RTL8214FCI-VC provides one Interrupt output pin to interrupt an external CPU for 10/100/1000Base-T ports. The polarity of the Interrupt output pin can be configured via register access. In configuration registers, each port has link-up and link-down interrupt flags with mask.

When port link-up or link-down interrupt mask is enabled, the RTL8214FCI-VC will raise the interrupt signal to alarm the external CPU. The CPU can read the interrupt flag to determine which port has changed to which status.

7.20. Reg.0.11 Power Down Mode

The RTL8214FCI-VC implements power down mode on a per-port basis. Setting MII Reg.0.11 forces the corresponding port of the RTL8214FCI-VC to enter power down mode.

7.21. Reg.0.14 PHY Digital Loopback Return to Internal

The digital loopback mode of the PHY (return to MAC) may be enabled on a per-port basis by setting MII Reg.0.14 to 1. In digital loopback mode, the TXD of the PHY is transferred directly to the RXD of the PHY, with TXEN changed to CRS_DV, and returns to the MAC via an internal MII. The data stream coming from the MAC will not egress to the physical medium, and an incoming data stream from the network medium will be blocked in this mode. The packets will be looped back in 10Mbps, 100Mbps, and 1000Mbps in full duplex mode. This function is useful for diagnostic purposes.

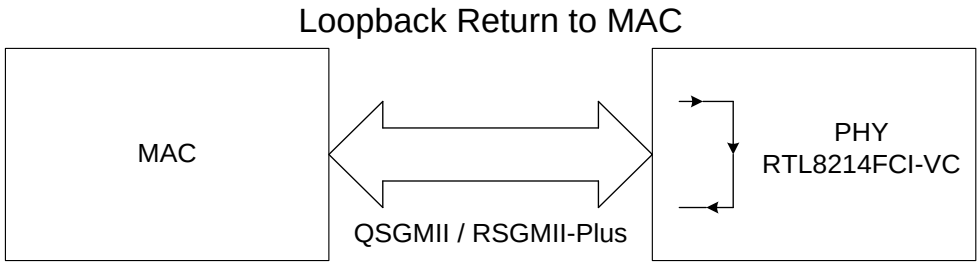


Figure 13. Reg.0.14 PHY Digital Loopback

As the RTL8214FCI-VC only supports digital loopback in full duplex mode, PHY Reg.0.8 for each port will be always kept to 1 when digital loopback is enabled. In loopback mode, the link LED of the loopback port should be always turned on, and the speed combined with the duplex LED will reflect the link status (1000full/100full/10full) correctly, regardless of what the previous status of this loopback port was.

8. Register Descriptions

Registers 0~15 of the MII are defined by the MII specification. Other registers are defined by Realtek Semiconductor Corp. for internal use and are reserved.

The following abbreviations are used in this section:

RW: Read/Write RO: Read Only SC: Self Clearing

LL: Latch Low until clear LH: Latch High until clear

Table 15. Register Descriptions

Page	Register	Description	Default
0	0	Control	0x1140
		1000Base-X	0x1140
		100Base-FX	0x2100
	1	Status	0x79C9
		1000Base-X	0x6109
		100Base-FX	0x6000
	2	PHY Identifier 1	0x001C
	3	PHY Identifier 2	0xC981
	4	Auto-Negotiation Advertisement	0x05E1
		1000Base-X Auto-Negotiation Advertisement	0x0020
	5	Auto-Negotiation Link Partner Ability	0x0000
		1000Base-X Auto-Negotiation Link Partner Ability	0x0000
	6	Auto-Negotiation Expansion	0x0064
	7	Auto-Negotiation Next Page Transmit	0x2001
	8	Auto-Negotiation Link Partner Next Page Ability	0x0000
	9	1000Base-T Control	0x0E00
	10	1000Base-T Status	0x0000
	11~12	Reserved	0x0000
	13	1000Base-T MMD access control	0x0000
	14	1000Base-T MMD access address data	0x0000
	15	Extended Status	0x2000
		1000Base-X Extended Status	0x8000
		100Base-FX Extended Status	0x8000
	16~30	ASIC Control	-

8.1. Register 0: Control

Table 16. Register 0: Control

Reg.bit	Name	Mode	Description	Default
0.15	Reset	RW/SC	1: PHY reset 0: Normal operation This bit is self-clearing.	0
0.14	Loopback (Digital loopback)	RW	1: Enable loopback (this will loopback TXD to RXD and ignore all activity on the cable media) 0: Normal operation This function is usable only when this PHY is operated in 10Base-T full duplex, 100Base-TX full duplex, or 1000Base-T full duplex.	0
0.13	Speed Selection[0]	RW	[0.6, 0.13] Speed Selection [1:0]. 11: Reserved 10: 1000Mbps 01: 100Mbps 00: 10Mbps This bit can be set through SMI (Read/Write).	0
0.12	Auto Negotiation Enable	RW	1: Enable auto-negotiation process 0: Disable auto-negotiation process This bit can be set through SMI (Read/Write).	1
0.11	Power Down	RW	1: Power down (all functions will be disabled except SMI function) 0: Normal operation	0
0.10	Isolate	RW	1: Electrically isolates the PHY from QGMII (PHY still responds to MDC/MDIO) 0: Normal operation	0
0.9	Restart Auto Negotiation	RW/SC	1: Restart Auto-Negotiation process 0: Normal operation	0
0.8	Duplex Mode	RW	1: Full duplex operation 0: Half duplex operation This bit can be set through SMI (Read/Write).	1
0.7	Collision Test	RO	1: Collision test enabled 0: Normal operation When set, this bit will cause the COL signal to be asserted in response to the assertion of TXEN within 512-bit times. The COL signal will be de-asserted within 4-bit times in response to the de-assertion of TXEN.	0
0.6	Speed Selection[1]	RW	See Bit 13.	1
0.[5:0]	Reserved	RO	Reserved.	000000

8.2. Register 1: Status

Table 17. Register 1: Status

Reg.bit	Name	Mode	Description	Default
1.15	100Base-T4	RO	0: No 100Base-T4 capability The RTL8214FCI-VC does not support 100Base-T4 mode, and this bit should always be 0.	0
1.14	100Base-TX-FD	RO	1: 100Base-TX full duplex capable 0: Not 100Base-TX full duplex capable	1
1.13	100Base-TX-HD	RO	1: 100Base-TX half duplex capable 0: Not 100Base-TX half duplex capable	1
1.12	10Base-T-FD	RO	1: 10Base-T full duplex capable 0: Not 10Base-TX full duplex capable	1
1.11	10Base-T-HD	RO	1: 10Base-T half duplex capable 0: Not 10Base-TX half duplex capable	1
1.10	100Base-T2-FD	RO	0: No 100Base-T2 full duplex capability The RTL8214FCI-VC does not support 100Base-T2 mode, and this bit should always be 0.	0
1.9	100Base-T2-HD	RO	0: No 100Base-T2 half duplex capability The RTL8214FCI-VC does not support 100Base-T2 mode, and this bit should always be 0.	0
1.8	Extended Status	RO	1: Extended status information in Register 15 The RTL8214FCI-VC always supports Extended Status Register.	1
1.7	Reserved	RO	Reserved.	1
1.6	MF Preamble Suppression	RO	The RTL8214FCI-VC will accept management frames with preamble suppressed.	1
1.5	Auto-negotiate Complete	RO	1: Auto-negotiation process completed 0: Auto-negotiation process not completed	0
1.4	Remote Fault	RO/ LH	1: Remote fault indication from link partner has been detected 0: No remote fault indication detected This bit will remain set until it is cleared by reading register 1 via the management interface.	0
1.3	Auto-Negotiation Ability	RO	1: Auto-negotiation capable (permanently=1) 0: No Auto-negotiation capability	1
1.2	Link Status	RO/ LL	1: Link has not failed since previous read 0: Link has failed since previous read If the link fails, this bit will be set to 0 until this bit is read.	0
1.1	Jabber Detect	RO/ LH	1: Jabber detected 0: No Jabber detected Jabber is supported only in 10Base-T mode.	0
1.0	Extended Capability	RO	1: Extended register capable (permanently=1) 0: Not extended register capable	1

8.3. Register 2: PHY Identifier 1

The PHY Identifier Registers #1 and #2 together form a unique identifier for the PHY part of this device. The Identifier consists of a concatenation of the Organizationally Unique Identifier (OUI), the vendor's model number, and the model revision number. A PHY may return a value of zero in each of the 32 bits of the PHY Identifier if desired. The PHY Identifier is intended to support network management.

Table 18. Register 2: PHY Identifier 1

Reg.bit	Name	Mode	Description	Default
2.[15:0]	OUI	RO	Composed of the 3rd to 18th Bits of the Organizationally Unique Identifier (OUI), Respectively.	0x001C

8.4. Register 3: PHY Identifier 2

Table 19. Register 3: PHY Identifier 2

Reg.bit	Name	Mode	Description	Default
3.[15:10]	OUI	RO	Assigned to the 19th through 24th Bits of the OUI.	110010
3.[9:4]	Model Number	RO	Manufacturer's Model Number.	011000
3.[3:0]	Revision Number	RO	Manufacturer's Revision Number.	0001

8.5. Register 4: Auto-Negotiation Advertisement

This register contains the advertisement abilities of this device as they will be transmitted to its Link Partner during Auto-negotiation.

Note: Each time the link ability of the RTL8214FCI-VC is reconfigured, the auto-negotiation process should be executed to allow the configuration to take effect.

Table 20. Register 4: Auto-Negotiation Advertisement

Reg.bit	Name	Mode	Description	Default
4.15	Next Page	RO	1: Additional next pages exchange desired 0: No additional next pages exchange desired	0
4.14	Acknowledge	RO	Permanently=0.	0
4.13	Remote Fault	RW	1: Advertises that the RTL8214FCI-VC has detected a remote fault 0: No remote fault detected	0
4.12	Reserved	RO	Reserved.	0
4.11	Asymmetric Pause	RW	1: Advertises that the RTL8214FCI-VC has asymmetric flow control capability 0: No asymmetric flow control capability	0
4.10	Pause	RW	1: Advertises that the RTL8214FCI-VC has flow control capability 0: No flow control capability	1
4.9	100Base-T4	RO	1: 100Base-T4 capable 0: Not 100Base-T4 capable (permanently=0)	0
4.8	100Base-TX-FD	RW	1: 100Base-TX full duplex capable 0: Not 100Base-TX full duplex capable	1

Reg.bit	Name	Mode	Description	Default
4.7	100Base-TX	RW	1: 100Base-TX half duplex capable 0: Not 100Base-TX half duplex capable	1
4.6	10Base-T-FD	RW	1: 10Base-TX full duplex capable 0: Not 10Base-TX full duplex capable	1
4.5	10Base-T	RW	1: 10Base-TX half duplex capable 0: Not 10Base-TX half duplex capable	1
4.[4:0]	Selector Field	RO	00001: IEEE 802.3	00001

Note 1: This Register 4 setting has no effect unless auto-negotiation is restarted or link down.
Note 2: If 1000Base-T is advertised, then the required next pages are automatically transmitted.

8.6. Register 4: 1000Base-X Auto-Negotiation Advertisement

Table 21. Register 4: 1000Base-X Auto-Negotiation Advertisement

Reg.bit	Name	Mode	Description	Default
4.15	Next Page	RO	1: Additional next pages exchange desired 0: No additional next pages exchange desired	0
4.14	Reserved	RO	Reserved	0
4.[13:12]	Remote Fault	RW	00: No Error, Link OK 01: Link Failure 10: Offline 11: Auto-Negotiation error	00
4.[11:9]	Reserved	RO	Reserved	000
4.8	Asymmetric Pause	RW	1: Advertises that the RTL8214FCI-VC has asymmetric flow control capability 0: No asymmetric flow control capability	0
4.7	Pause	RW	1: Advertises that the RTL8214FCI-VC has flow control capability 0: No flow control capability	0
4.6	Half_Duplex	RW	1: Half duplex capable 0: Not half duplex capable	0
4.5	Full Duplex	RW	1: Full duplex capable 0: Not full duplex capable	1
4.[4:0]	Reserved	RO	Reserved	00000

8.7. Register 5: Auto-Negotiation Link Partner Ability

This register contains the advertised abilities of the Link Partner as received during Auto-negotiation. The content changes after a successful Auto-negotiation.

Table 22. Register 5: Auto-Negotiation Link Partner Ability

Reg.bit	Name	Mode	Description	Default
5.15	Next Page	RO	1: Link partner desires Next Page transfer 0: Link partner does not desire Next Page transfer	0
5.14	Acknowledge	RO	1: Link Partner acknowledges reception of Fast Link Pulse (FLP) 0: Not acknowledged by Link Partner	0
5.13	Remote Fault	RO	1: Remote Fault indicated by Link Partner 0: No remote fault indicated by Link Partner	0
5.12	Reserved	RO	Technology Ability Field. Received code word bit 12.	0
5.11	Asymmetric Pause	RO	1: Asymmetric Flow control supported by Link Partner 0: No Asymmetric flow control supported by Link Partner When auto-negotiation is enabled, this bit reflects Link Partner ability (Read only).	0
5.10	Pause	RO	1: Flow control supported by Link Partner 0: No flow control supported by Link Partner When auto-negotiation is enabled, this bit reflects Link Partner ability (Read only).	0
5.9	100Base-T4	RO	1: 100Base-T4 supported by Link Partner 0: 100Base-T4 not supported by Link Partner	0
5.8	100Base-TX-FD	RO	1: 100Base-TX full duplex supported by Link Partner 0: 100Base-TX full duplex not supported by Link Partner	0
5.7	100Base-TX	RO	1: 100Base-TX half duplex supported by Link Partner 0: 100Base-TX half duplex not supported by Link Partner	0
5.6	10Base-T-FD	RO	1: 10Base-TX full duplex supported by Link Partner 0: 10Base-TX full duplex not supported by Link Partner	0
5.5	10Base-T	RO	1: 10Base-TX half duplex supported by Link Partner 0: 10Base-TX half duplex not supported by Link Partner	0
5.[4:0]	Selector Field	RO	00001: IEEE 802.3	00000

8.8. Register 6: Auto-Negotiation Expansion

Table 23. Register 6: Auto-Negotiation Expansion

Reg.bit	Name	Mode	Description	Default
6.[15:7]	Reserved	RO	Ignore On Read.	0
6.6	Receive Next Page Location Able	RO	1: Received next page storage location is specified by bit (6.5) 0: Received next page storage location is not specified by bit (6.5)	1
6.5	Received Next Page Storage Location	RO	1: Link Partner next pages are stored in Register 8 0: Link Partner next pages are stored in Register 5	1
6.4	Parallel Detection Fault	RO/LH	1: A fault has been detected via the Parallel Detection function 0: No fault has been detected via the Parallel Detection function	0
6.3	Link Partner Next Page Ability	RO	1: Link Partner is Next Page able 0: Link Partner is not Next Page able	0
6.2	Local Next Page Ability	RO	1: RTL8214FCI-VC is Next Page able	1
6.1	Page Received	RO/LH	1: A New Page has been received 0: A New Page has not been received	0
6.0	Link Partner Auto-Negotiation Ability	RO	If Auto-Negotiation is Enabled, this bit means: 1: Link Partner is Auto-Negotiation able 0: Link Partner is not Auto-Negotiation able	0

8.9. Register 7: Auto-Negotiation Next Page Transmit

Table 24. Register 7: Auto-Negotiation Next Page Transmit

Reg.bit	Name	Mode	Description	Default
7.15	Next Page	RW	1: Another next page desired 0: No other next page to send	0
7.14	Reserved	RO	1: A fault has been detected via the Parallel Detection function 0: No fault has been detected via the Parallel Detection function	0
7.13	Message Page	RW	1: Message page	1
7.12	Acknowledge 2	RW	1: Local device has the ability to comply with the message received 0: Local device has no ability to comply with the message received	0
7.11	Toggle	RO	Toggle Bit.	0
7.[10:0]	Message/Unformatted Field	RW	Content of Message/Unformatted Page.	00000000001

8.10. Register 8: Auto-Negotiation Link Partner Next Page Ability

Table 25. Register 8: Auto-Negotiation Link Partner Next Page Ability

Reg.bit	Name	Mode	Description	Default
8.15	Next Page	RO	Received Link Code Word Bit 15.	0
8.14	Acknowledge	RO	Received Link Code Word Bit 14.	0
8.13	Message Page	RO	Received Link Code Word Bit 13.	0
8.12	Acknowledge 2	RO	Received Link Code Word Bit 12.	0
8.11	Toggle	RO	Received Link Code Word Bit 11.	0
8.[10:0]	Message/Unformatted Field	RO	Received Link Code Word Bit 10:0.	0

8.11. Register 9: 1000Base-T Control

Table 26. Register 9: 1000Base-T Control

Reg.bit	Name	Mode	Description	Default
9.[15:13]	Test Mode	RW	Test Mode Select. 000: Normal mode 001: Test mode 1–Transmit waveform test 010: Test mode 2–Transmit jitter test in MASTER mode 011: Test mode 3–Transmit jitter test in SLAVE mode 100: Test mode 4–Transmitter distortion test 101, 110, 111: Reserved	000
9.12	MASTER/SLAVE Manual Configuration Enable	RW	1: Enable MASTER/SLAVE manual configuration 0: Disable MASTER/SLAVE manual configuration	0
9.11	MASTER/SLAVE Configuration Value	RW	1: Configure PHY as MASTER during MASTER/SLAVE negotiation, only when 9.12 is set to logical one 0: Configure PHY as SLAVE during MASTER/SLAVE negotiation, only when 9.12 is set to logical one	1
9.10	Port Type	RW	1: Multi-port device 0: Single-port device	1
9.9	1000Base-T Full-Duplex	RW	1: Advertise PHY is 1000Base-T Full-Duplex capable 0: Advertise PHY is not 1000Base-T Full-Duplex capable	1
9.8	1000Base-T Half-Duplex	RW	1: Advertise PHY is 1000Base-T Half-Duplex capable 0: Advertise PHY is not 1000Base-T Half-Duplex capable	0
9.[7:0]	Reserved	RW	Reserved.	0

8.12. Register 10: 1000Base-T Status

Table 27. Register 10: 1000Base-T Status

Reg.bit	Name	Mode	Description	Default
10.15	MASTER/SLAVE Configuration Fault	RO/LH/SC	1: MASTER/SLAVE configuration fault detected 0: No MASTER/SLAVE configuration fault detected	0
10.14	MASTER/SLAVE Configuration Resolution	RO	1: Local PHY configuration resolved to MASTER 0: Local PHY configuration resolved to SLAVE	0
10.13	Local Receiver Status	RO	1: Local receiver OK 0: Local receiver not OK	0
10.12	Remote Receiver Status	RO	1: Remote receiver OK 0: Remote receiver not OK	0
10.11	Link Partner 1000Base-T Full-Duplex	RO	1: Link partner is capable of 1000Base-T Full-Duplex 0: Link partner is not capable of 1000Base-T Full-Duplex	0
10.10	1000Base-T Half-Duplex	RO	1: Link partner is capable of 1000Base-T Half-Duplex 0: Link partner is not capable of 1000Base-T Half-Duplex	0
10.[9:8]	Reserved	RO	Reserved.	0
10.[7:0]	Idle Error Count	RO/SC	Idle Error Counter. The counter stops automatically when it reaches 0xFF.	0

8.13. Register 13: MMD Access Control Register

Table 28. Register 13: MMD Access Control Register

Reg.bit	Name	Mode	Description	Default
13.[15:14]	Function	RW	13.[15:14] 00: Address 01: Data, no post increment 10: Data, post increment on read and writes 11: Data, post increment on writes only	0
13.[13:5]	Reserved	RW	Write as 0, ignore on read	0
13.[4:0]	MMD DEVAD	RW	Device address	0

8.14. Register 14: MMD Access Address Data Register

Table 29. Register 14: MMD Access Address Data Register

Reg.bit	Name	Mode	Description	Default
13.[15:10]	MMD Address Data	RW	If 13.[15:14] = 00, MMD DEVAD's address register. Otherwise, MMD DEVAD's data register as indicated by the content of its address register	0

8.15. Register 15: Extended Status

Table 30. Register 15: Extended Status

Reg.bit	Name	Mode	Description	Default
15.15	1000Base-X Full-Duplex	RO	1: 1000Base-X Full-Duplex capable 0: Not 1000Base-X Full-Duplex capable	0
15.14	1000Base-X Half-Duplex	RO	1: 1000Base-X Half-Duplex capable 0: Not 1000Base-X Half-Duplex capable	0
15.13	1000Base-T Full-Duplex	RO	1: 1000Base-T Full-Duplex capable 0: Not 1000Base-T Full-Duplex capable	1
15.12	1000Base-T Half-Duplex	RO	1: 1000Base-T Half-Duplex capable 0: Not 1000Base-T Half-Duplex capable	0
15.[11:0]	Reserved	RO	Reserved.	0

9. Electrical Characteristics

9.1. Absolute Maximum Ratings

WARNING: Absolute maximum ratings are limits beyond which permanent damage may be caused to the device, or device reliability may be affected. All voltages are specified reference to GND unless otherwise specified.

Table 31. Absolute Maximum Ratings

Parameter	Min	Max	Units
Junction Temperature (Tj)	-	+125	°C
Storage Temperature	-45	+125	°C
DVDDIO, AVDDH Supply Voltage Referenced to GND	GND-0.3	+3.63	V
DVDDL, AVDDL, SVDDL, PLLVDDL Supply Voltage Referenced to GND	GND-0.3	+1.21	V
Digital Input Voltage	GND-0.3	VDDIO+0.3	V

9.2. Operating Range

Table 32. Operating Range

Parameter	Min	Typ	Max	Units
Ambient Operating Temperature (Ta)	-40	-	85	°C
DVDDIO, AVDDH Supply Voltage Range	3.135	3.3	3.465	V
DVDDL, AVDDL, SVDDL, PLLVDDL Supply Voltage Range	1.05	1.1	1.15	V

9.3. Power Consumption

Table 33. Power Consumption

Parameter	Symbol	Min	Typ	Max	Units
System Idle (All ports are in link-down state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	83	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	510	-	mA
1000Base-T Active (4 1000base-T Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	240	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	978	-	mA
EEE 1000Base-T Active (4 1000base-T Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	79	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	616	-	mA
1000Base-X Active (4 1000base-X Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	83	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	542	-	mA
100Base-TX Active (4 100base-TX Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	139	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	611	-	mA
100Base-FX Active (4 100base-FX Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	83	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	520	-	mA
10Base-T Active (4 10base-T Ports are in link-up state)					
Power Supply Current for VDDH	I_{DVDDIO}, I_{AVDDH}, I_{SVDDH}	-	183	-	mA
Power Supply Current for VDDL	I_{DVDDL}, I_{AVDDL}, I_{SVDDL}, $I_{PLLVDDL}$	-	524	-	mA
DVDDIO=3.3V					
TTL Input High Voltage	V_{IH}	2.0	-	-	V
TTL Input Low Voltage	V_{IL}	-	-	0.7	V
Output High Voltage	V_{OH}	2.7	-	-	V
Output Low Voltage	V_{OL}	-	-	0.6	V

Note: DVDDIO=3.3V, AVDDH=3.3V, DVDDL=1.10V, AVDDL=1.10V, SVDDL=1.10V.

9.4. IEEE 10/100/1000Base-T Specifications

Table 34. IEEE 10/100/1000Base-T Specifications

Parameter	Min	Typ	Max	Units
1000Base-T				
Peak Voltage of Point A	670	724.5	820	mV
Peak Voltage of Point B	670	726.0	820	mV
Difference between the Peak Voltage of Point A and Point B	-	0.467	1	%
Difference between the Peak Voltage of Point C and 0.5 Times the Average of the Peak Voltage of Points A and B	-	0.47	2	%
Difference between the Peak Voltage of Point D and 0.5 Times the Average of the Peak Voltage of Points A and B	-	0.66	2	%
Droop of Point G	73.1	85.4	-	%
Droop of Point J	73.1	826	-	%
Transmitter Distortion	-	8.5	10	mV
Common Mode Output Voltage	-	46.4	50	mV
100Base-TX				
Peak Voltage (+Vout)	950	1017	1050	mV
Peak Voltage (-Vout)	-950	-1017	-1050	mV
Amplitude Symmetry	0.98	1.001	1.02	-
Rise Time (+Vout)	3	3.56	5	ns
Rise Time (-Vout)	3	3.51	5	ns
Fall Time (+Vout)	3	3.54	5	ns
Fall Time (-Vout)	3	3.48	5	ns
Rise/Fall Symmetry (+Vout)	-	70.2	500	ps
Rise/Fall Symmetry (-Vout)	-	70.1	500	ps
Overshoot (+Vout)	-	0.8	5	%
Overshoot (-Vout)	-	1.1	5	%
Transmit Jitter (+Vout)	-	0.62	1.4	ns
Transmit Jitter (-Vout)	-	0.61	1.4	ns
Distortion (Duty Cycle)	-	80	500	ps
10Base-T				
Link Pulse Timing	8	16	24	ms
Differential Voltage	2.2	2.57	2.8	V
Peak-to-Peak Normal Jitter with Cable	-	1.7	11	ns
Peak-to-Peak 8.0 BT Jitter with Cable	-	8.2	22	ns
Peak-to-Peak 8.5 BT Jitter with Cable	-	11.73	22	ns
Peak-to-Peak Normal Jitter without Cable	-	0.9	16	ns
Peak-to-Peak 8.0 BT Jitter without Cable	-	1.2	40	ns
Peak-to-Peak 8.5 BT Jitter without Cable	-	1.3	40	ns
Common Mode Output Voltage	-	23.55	50	mV

9.5. QSGMII Characteristics

9.5.1. QSGMII Differential Transmitter Characteristics

Table 35. QSGMII Differential Transmitter Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Notes
UI	Unit Interval	199.94	200	200.06	ps	200ps ± 300ppm
T_X1	Eye Mask	-	-	0.175	UI	-
T_X2	Eye Mask	-	-	0.4	UI	-
T_Y1	Eye Mask	150	-	-	mV	-
T_Y2	Eye Mask	-	-	650	mV	-
$V_{TX-OFFSET}$	Output Offset Voltage	600	TBD	1000	mV	-
$V_{TX-DIFFp-p}$	Output Differential Voltage	400	800	1300	mV	-
T_{TX-EYE}	Minimum TX Eye Width	0.6	-	-	UI	-
$T_{TX-JITTER}$	Output Jitter	-	-	0.35	UI	$T_{TX-JITTER-MAX}$=1 - $T_{TX-EYE-MIN}$=0.35UI
$T_{TX-RISE}$	Output Rise Time	0.15	-	-	UI	20% ~ 80%
$T_{TX-FALL}$	Output Fall Time	0.15	-	-	UI	20% ~ 80%
R_{TX}	Differential Resistance	80	100	120	ohm	-
C_{TX}	AC Coupling Capacitor	80	100	120	nF	-
L_{TX}	Transmit Length in PCB	-	-	10	inch	-

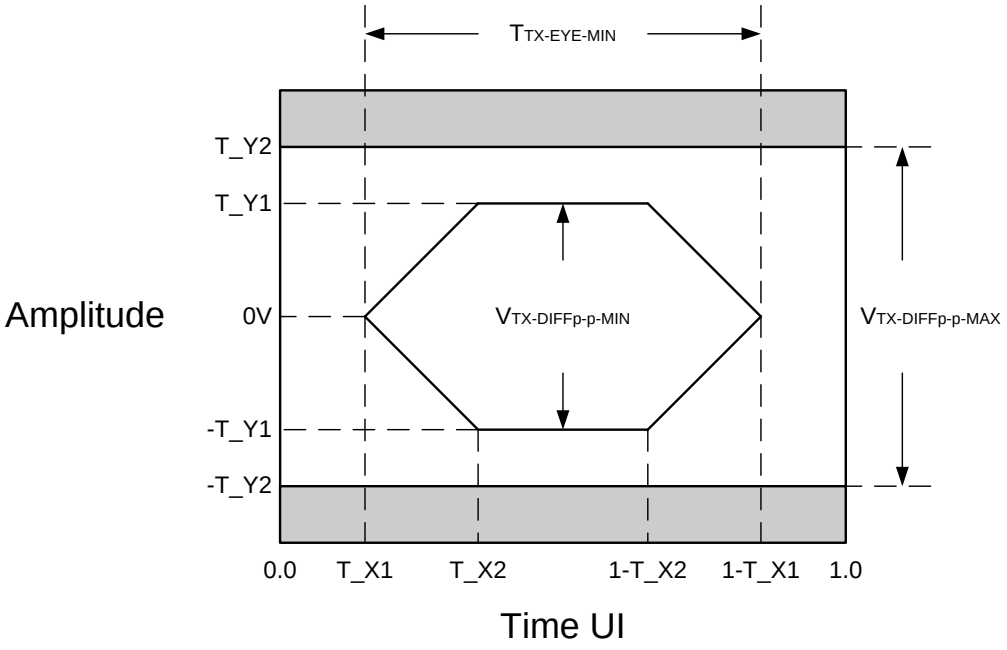


Figure 14. QSGMII Differential Transmitter Eye Diagram

9.5.2. QSGMII Differential Receiver Characteristics

Table 36. QSGMII Differential Receiver Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Notes
UI	Unit Interval	199.94	200	200.06	ps	200ps ± 300ppm
R_X1	Eye Mask	-	-	0.3	UI	-
R_Y1	Eye Mask	100	-	-	mV	-
R_Y2	Eye Mask	-	-	650	mV	-
$V_{RX-DIFFp-p}$	Input Differential Voltage	200	-	1300	mV	-
T_{RX-EYE}	Minimum RX Eye Width	0.4	-	-	UI	-
$T_{RX-JITTER}$	Input Jitter Tolerance	-	-	0.6	UI	$T_{RX-JITTER-MAX}$=1 - $T_{RX-EYE-MIN}$=0.6UI
R_{RX}	Differential Resistance	80	100	120	ohm	-

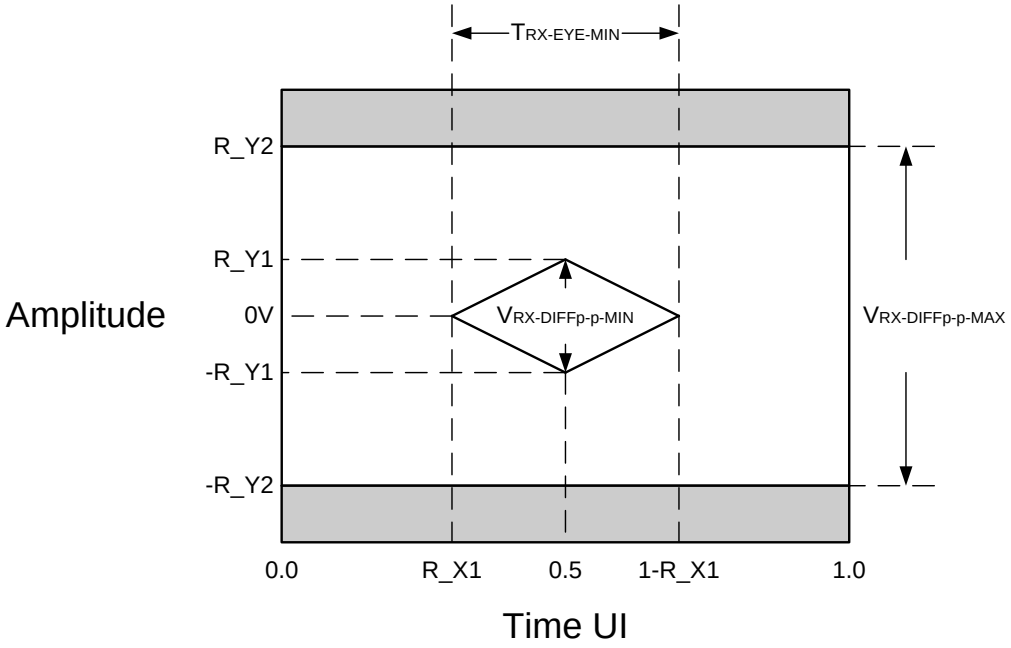


Figure 15. QSGMII Differential Receiver Eye Diagram

9.6. RSGMII-Plus Characteristics

9.6.1. RSGMII-Plus Differential Transmitter Characteristics

Table 37. RSGMII-Plus Differential Transmitter Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Notes
UI	Unit Interval	199.94	200	200.06	ps	200ps ± 300ppm
T_X1	Eye Mask	-	-	0.175	UI	-
T_X2	Eye Mask	-	-	0.4	UI	-
T_Y1	Eye Mask	200	-	-	mV	-
T_Y2	Eye Mask	-	-	450	mV	-
$V_{TX-OFFSET}$	Output Offset Voltage	600	TBD	1000	mV	-
$V_{TX-DIFFp-p}$	Output Differential Voltage	400	800	1300	mV	-
T_{TX-EYE}	Minimum TX Eye Width	0.6	-	-	UI	-
$T_{TX-JITTER}$	Output Jitter	-	-	0.35	UI	$T_{TX-JITTER-MAX}$=1 - $T_{TX-EYE-MIN}$=0.35UI
$T_{TX-RISE}$	Output Rise Time	0.15	-	-	UI	20% ~ 80%
$T_{TX-FALL}$	Output Fall Time	0.15	-	-	UI	20% ~ 80%
R_{TX}	Differential Resistance	80	100	120	ohm	-
C_{TX}	AC Coupling Capacitor	80	100	120	nF	-
L_{TX}	Transmit Length in PCB	-	-	10	inch	-

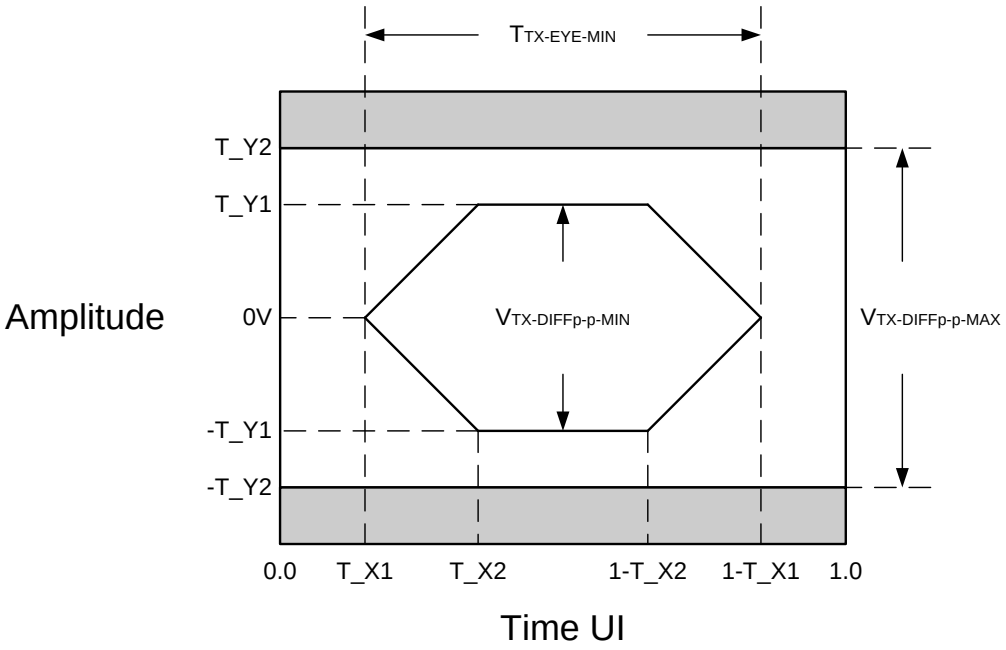


Figure 16. RSGMII-Plus Differential Transmitter Eye Diagram

9.6.2. RSGMII-Plus Differential Receiver Characteristics

Table 38. RSGMII-Plus Differential Receiver Characteristics

Symbol	Parameter	Min	Typ	Max	Units	Notes
UI	Unit Interval	199.94	200	200.06	ps	200ps ± 300ppm
R_X1	Eye Mask	-	-	0.3	UI	-
R_Y1	Eye Mask	100	-	-	mV	-
R_Y2	Eye Mask	-	-	600	mV	-
$V_{RX-DIFFp-p}$	Input Differential Voltage	200	-	1300	mV	-
T_{RX-EYE}	Minimum RX Eye Width	0.4	-	-	UI	-
$T_{RX-JITTER}$	Input Jitter Tolerance	-	-	0.6	UI	$T_{RX-JITTER-MAX}$=1 - $T_{RX-EYE-MIN}$=0.6UI
R_{RX}	Differential Resistance	80	100	120	ohm	-

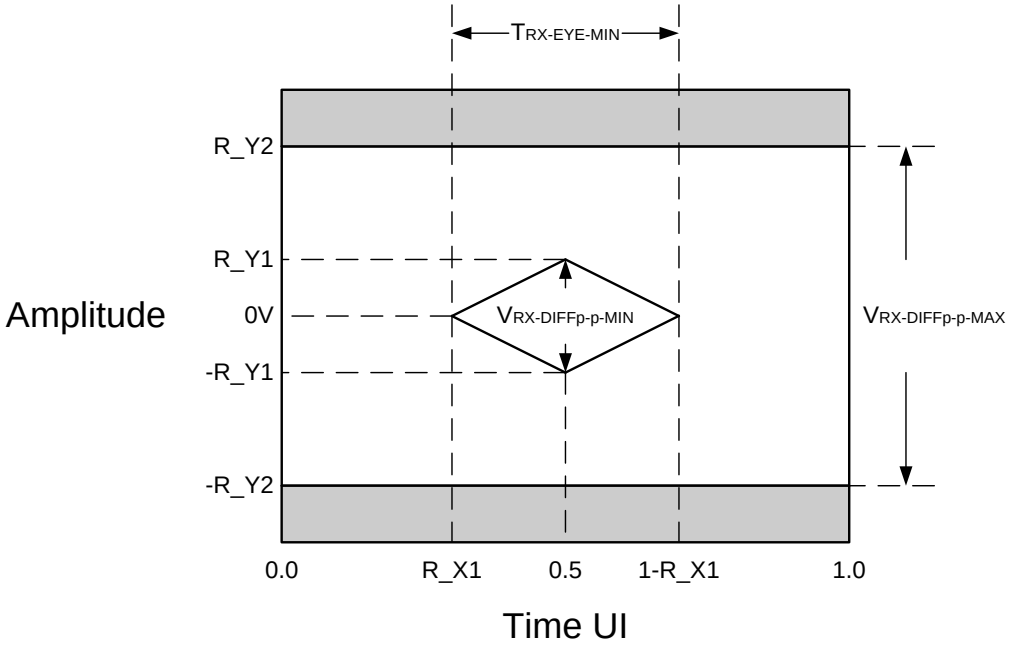


Figure 17. RSGMII-Plus Differential Receiver Eye Diagram

9.7. 1000Base-X Characteristics

9.7.1. 1000Base-X Differential Transmitter Characteristics

Table 39. 1000Base-X Differential Transmitter Characteristics

Symbol	Description	Min	Typ	Max	Units	Note
UI	Unit Interval	799.76	800	800.24	ps	800 +/- 300ppm
T_X1	Eye Mask	-	-	0.15	UI	-
T_X2	Eye Mask	-	-	0.4	UI	-
T_Y1	Eye Mask	250	-	-	mV	-
T_Y2	Eye Mask	-	-	600	mV	-
$V_{TX-OFFSET}$	Output Offset Voltage	600	800	1000	mV	-
$V_{TX-DIFFp-p}$	Output Differential Voltage	500	700	1200	mV	-
V_{TX-EYE}	Minimum TX Eye Width	0.7	-	-	UI	-
$V_{TX-JITTER}$	Output Jitter	-	-	0.3	UI	-
$V_{TX-RISE}$	Output Rise Time	0.035	-	-	UI	-
$V_{TX-FALL}$	Output Fall Time	0.035	-	-	UI	-
R_{TX}	Differential Resistance	80	100	120	Ohm	-
C_{TX}	AC Coupling Capacitor	80	100	120	nF	-
L_{TX}	Transmit Length in PCB	-	-	10	Inch	-

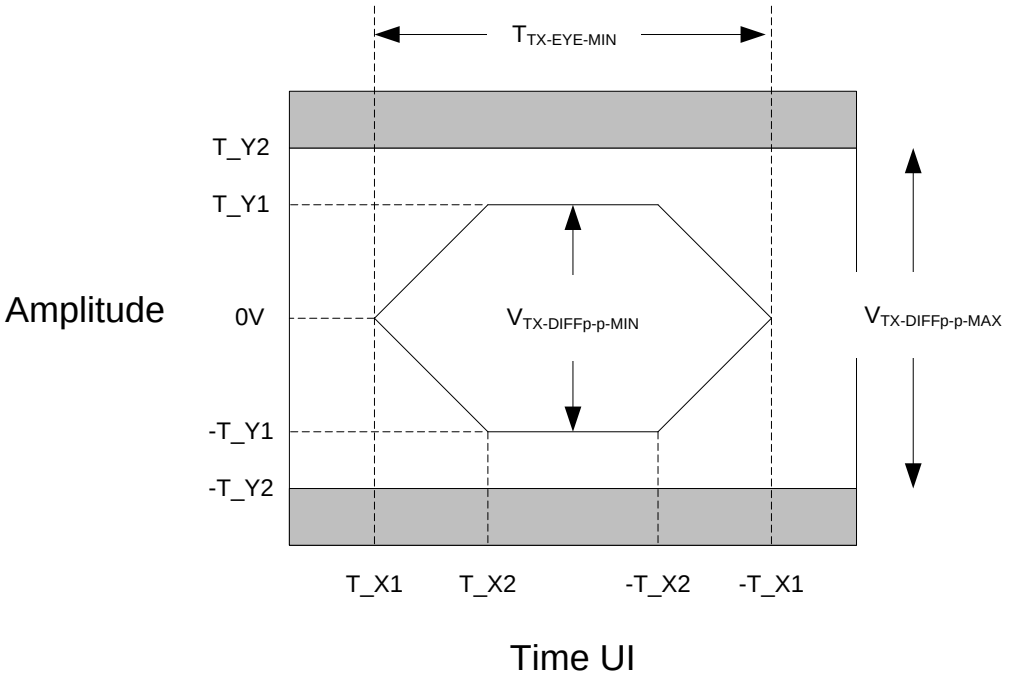


Figure 18. 1000Base-X Differential Transmitter Eye Diagram

9.7.2. 1000Base-X Differential Receiver Characteristics

Table 40. 1000Base-X Differential Receiver Characteristics

Symbol	Description	Min	Typ	Max	Units	Note
UI	Unit Interval	799.76	800	800.24	ps	800 +/- 300ppm
R_X1	Eye Mask	-	-	0.3	UI	-
R_Y1	Eye Mask	100	-	-	mV	-
R_Y2	Eye Mask	-	-	1000	mV	-
$V_{RX-DIFFp-p}$	Input Differential Voltage	200	-	2000	mV	-
V_{RX-EYE}	Minimum TX Eye Width	0.4	-		UI	-
$V_{TX-JITTER}$	Input Jitter Tolerance	-	-	0.6	UI	$T_{RX-JITTER-MAX}$=1 – $T_{RX-EYE-MIN}$ = 0.6UI
R_{TX}	Differential Resistance	80	100	120	Ohm	-

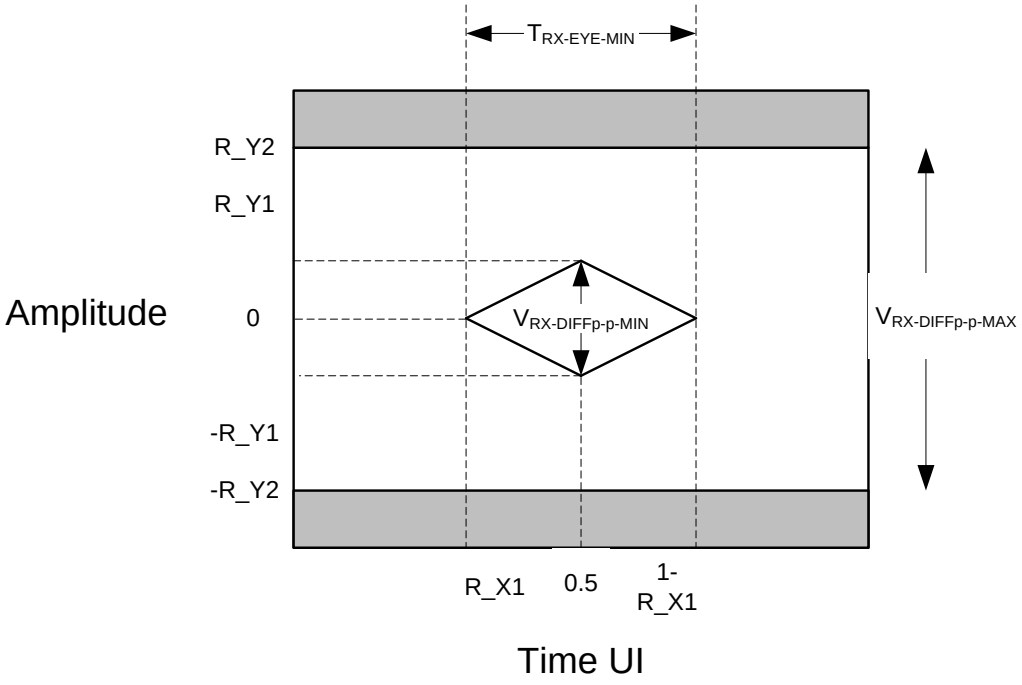


Figure 19. 1000Base-X Differential Receiver Eye Diagram

9.8. 100Base-FX Characteristics

9.8.1. 100Base-FX Differential Transmitter Characteristics

Table 41. 100Base-FX Differential Transmitter Characteristics

Symbol	Description	Min	Typ	Max	Units	Note
UI	Unit Interval	7.9976	8	8.0024	ns	8ns +/- 300ppm
T_X1	Eye Mask	-	-	0.15	UI	-
T_X2	Eye Mask	-	-	0.4	UI	-
T_Y1	Eye Mask	250	-	-	mV	-
T_Y2	Eye Mask	-	-	600	mV	-
$V_{TX-OFFSET}$	Output Offset Voltage	600	800	1000	mV	-
$V_{TX-DIFFp-p}$	Output Differential Voltage	500	700	1200	mV	-
V_{TX-EYE}	Minimum TX Eye Width	0.7	-	-	UI	-
$V_{TX-JITTER}$	Output Jitter	-	-	0.3	UI	$T_{TX-JITTER-MAX}$=1 – $T_{TX-EYE-MIN}$ = 0.35UI
$V_{TX-RISE}$	Output Rise Time	0.0035	-	-	UI	20% ~ 80%
$V_{TX-FALL}$	Output Fall Time	0.0035	-	-	UI	20% ~ 80%
R_{TX}	Differential Resistance	80	100	120	Ohm	-
C_{TX}	AC Coupling Capacitor	80	100	120	nF	-
L_{TX}	Transmit Length in PCB	-	-	10	Inch	-

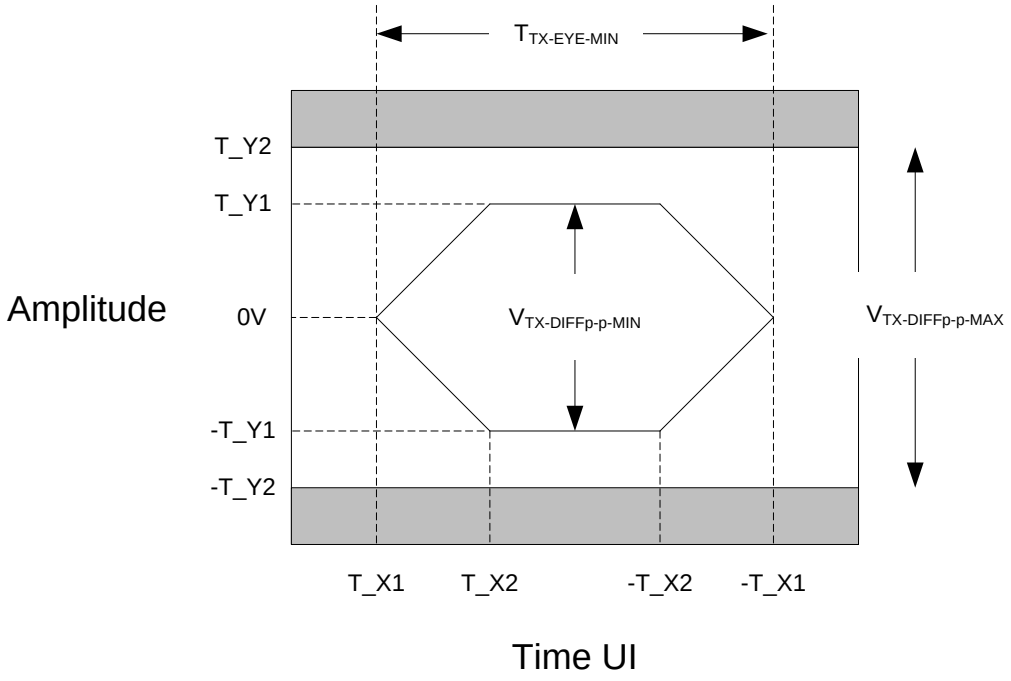


Figure 20. 100Base-FX Differential Transmitter Eye Diagram

9.8.2. 100Base-FX Differential Receiver Characteristics

Table 42. 100Base-FX Differential Receiver Characteristics

Symbol	Description	Min	Typ	Max	Units	Note
UI	Unit Interval	7.9976	8	8.20024	ns	8ns +/- 300ppm
R_X1	Eye Mask	-	-	0.3	UI	-
R_Y1	Eye Mask	100	-	-	mV	-
R_Y2	Eye Mask	-	-	1000	mV	-
$V_{RX-DIFFp-p}$	Input Differential Voltage	200	-	2000	mV	-
V_{RX-EYE}	Minimum TX Eye Width	0.4	-	-	UI	-
$V_{TX-JITTER}$	Input Jitter Tolerance	-	-	0.6	UI	$T_{RX-JITTER-MAX}$=1 – $T_{RX-EYE-MIN}$ = 0.6UI
R_{TX}	Differential Resistance	80	100	120	Ohm	-

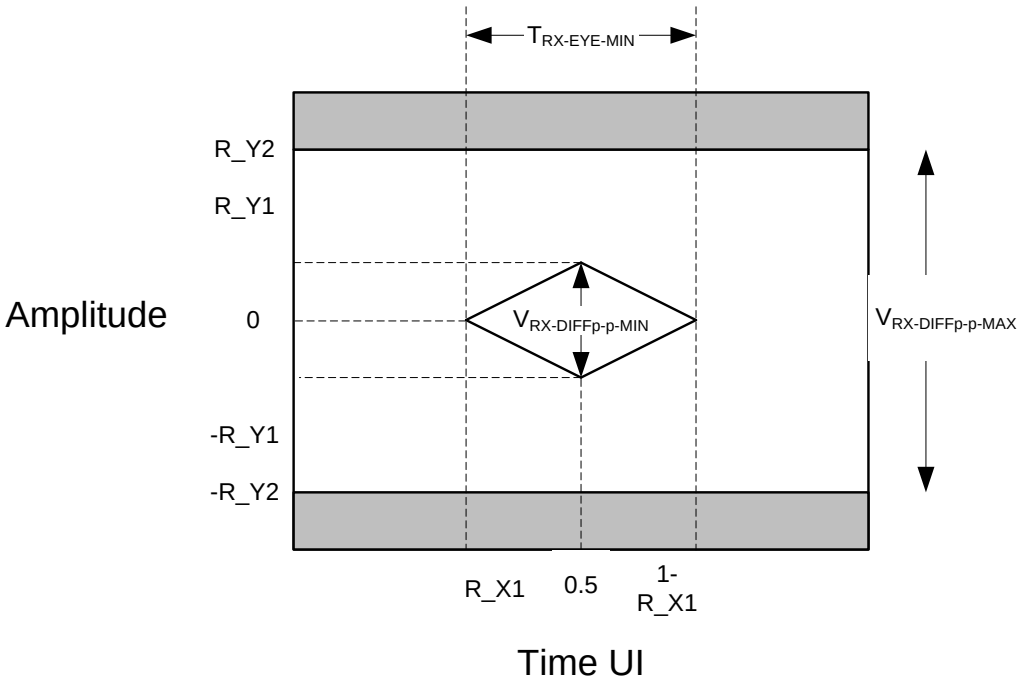


Figure 21. 100Base-FX Differential Receiver Eye Diagram

9.9. XTALI Clock Characteristics

Table 43. XTALI Clock Characteristics

Parameter	Min	Typ	Max	Units
Frequency of XTALI	-	25	-	MHz
Frequency Tolerance of XTALI	-50	-	+50	ppm
Duty Cycle of XTALI	40	-	60	%
Rise Time of XTALI	-	-	12.5	ns
Fall Time of XTALI	-	-	12.5	ns
Jitter of XTALI	-	-	200	ps

Note: PLL generated clocks are not recommended as input to XTALI since they can have excessive jitter. Zero delay buffers are also not recommended for the same reason.

9.10. Reset Characteristics

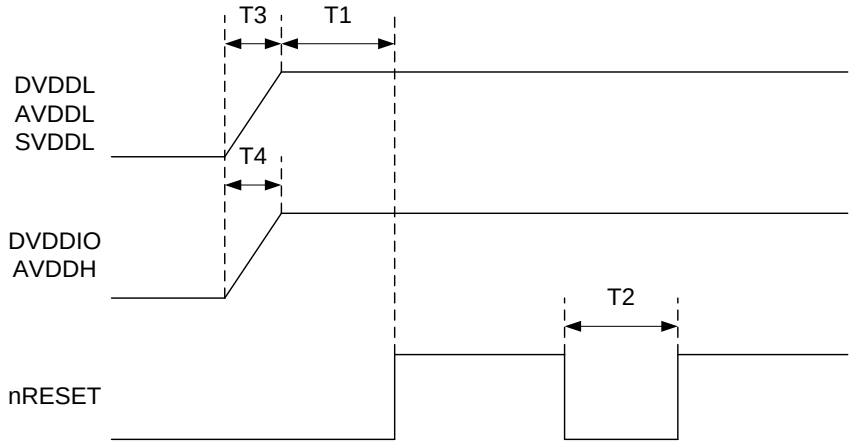


Figure 22. Power and Reset Characteristics

Table 44. Power and Reset Characteristics

Parameter	SYM	Description/Condition	Type	Min	Typical	Max	Units
Reset Delay Time	t1	The duration from 'all power steady' to the reset signal released to high	I	10	-	-	ms
Reset Low Time	t2	The duration of reset signal remaining low time before issuing a reset to the RTL8214FCI-VC	I	10	-	-	ms
VDDL Power Rise Settling Time	t3	DVDDL, AVDDL, and SVDDL power rise settling time	I	1	-	-	ms
VDDH Power Rise Settling Time	t4	DVDDIO, and AVDDH power rise settling time	I	1	-	-	ms

9.11. MDC/MDIO Interface Characteristics

The RTL8214FCI-VC supports the IEEE compliant Management Data Input/Output (MDIO) Interface. This is the only method for the MAC to acquire the status of the PHY. The MDIO is a bi-directional signal that can be sourced by the Master or the Slave. In a write command, the master sources the MDIO signal. In a read command, the slave sources the MDIO signal.

- The timing characteristics t1, t2, and t3 (Figure 23) of the Master (MAC) are provided by the Master when the Master sources the MDIO signal (Write command)
- The timing characteristics t4 (Figure 24) of the Slave (RTL8214FCI-VC) are provided by the RTL8214FCI-VC when the RTL8214FCI-VC sources the MDIO signal (Read command)

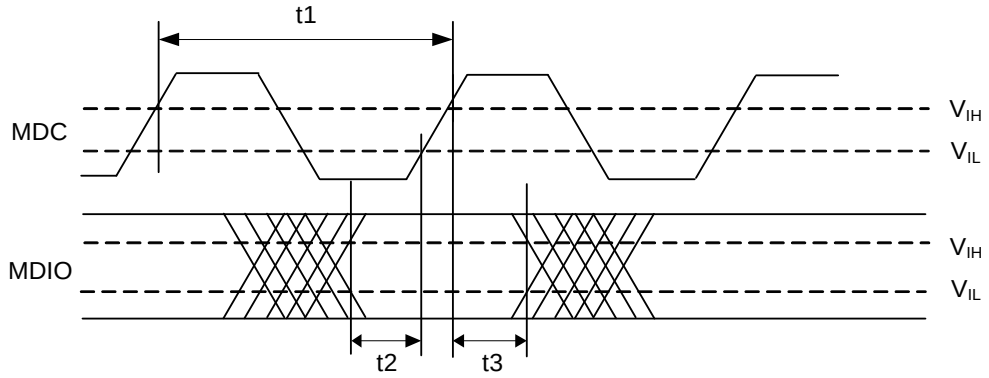


Figure 23. MDIO Sourced by Master (MAC)

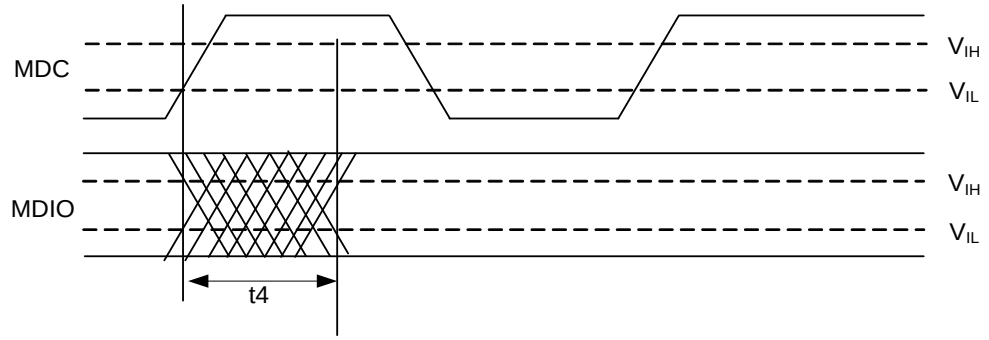


Figure 24. MDIO Sourced by RTL8214FCI-VC (Slave)

Table 45. MDIO Timing Characteristics and Requirement

Parameter	SYM	Description/Condition	Type	Min	Typical	Max	Units
MDC Clock Period	t1	Clock Period	I	125	-	-	ns
MDIO to MDC Rising Setup Time (Write Data)	t2	Input Setup Time	I	10	-	-	ns
MDIO to MDC Rising Hold Time (Write Data)	t3	Input Hold Time	I	10	-	-	ns
MDC to MDIO Delay Time (Read Data)	t4	Clock Rising Edge) to Data Delay Time	O	20	-	100	ns

9.12. LED Characteristics

9.12.1. Serial LED Timing

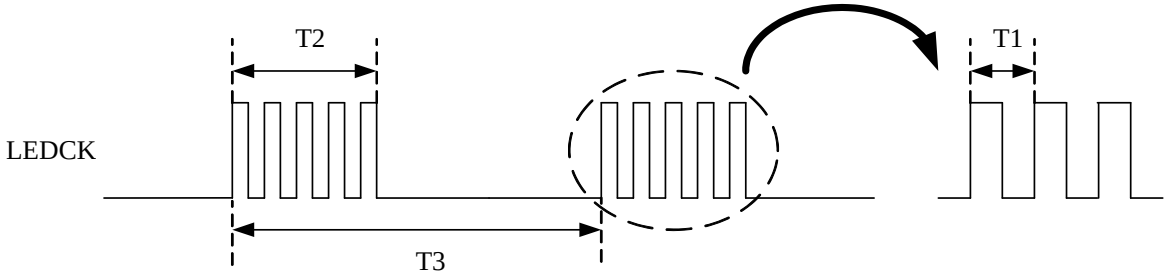


Figure 25. Serial LED Timing

Table 46. Serial LED Timing

Symbol	Description	Min	Typ	Max	Units
T1	Serial LED Clock Cycle Time	-	192	-	ns
T2	Serial LED Clock On/Off Duration	-	6.82	-	µs
T3	Serial LED Burst Cycle Time	-	32	-	ms

10. Thermal Characteristics

10.1. Assembly Description

Table 47. Assembly Description

Package	**Type**	E-Pad TQFP-176
	Dimension (L×W)	20×20mm
	Thickness	1.0mm
PCB	**PCB Dimension (L×W)**	180×130mm
	PCB Thickness	1.6mm
	Number of Cu Layer-PCB	2-Layer (2S) 4-Layer (2S2P)
Heat Sink	**AL6063T5**	31x 29 x 9.4 mm

10.2. Material Properties

Table 48. Material Properties

Item		**Material**	**Thermal Conductivity K (W/m-k)**
Package	**Die**	Si	149
	Epoxy	CRM-1076WA	0.9
	Lead Frame	C7025	172
	Mold Compound	G631M	0.9
PCB		Cu	389
		FR4	0.3

10.3. Simulation Conditions

Table 49. Simulation Conditions

Input Power	TBD
Test Board (PCB)	2L (2S)/4L (2S2P)
Control Condition	Air Flow = 0m/s

10.4. Thermal Performance of E-Pad TQFP-176 on PCB under Still Air Convention

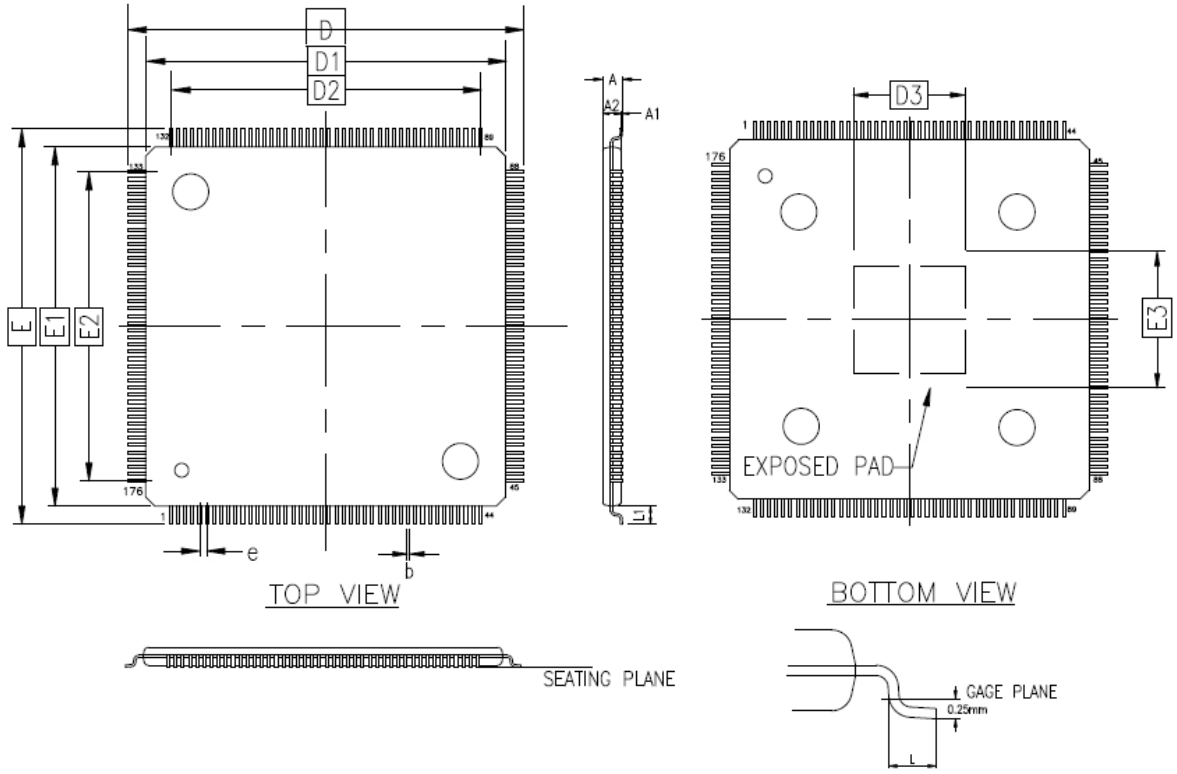
Table 50. Thermal Performance of E-Pad TQFP-176 on PCB under Still Air Convention

PCB Layer	θ_{JA}	θ_{JC}	Ψ_{JT}	Ψ_{JB}
4L PCB	15.05	9.51	4.99	8.71
2L PCB	21.48	10.43	6.92	12

Note:
θ_{JA}: Junction to ambient thermal resistance.
θ_{JC}: Junction to case thermal resistance.
Ψ_{JT}: Junction to top center of package thermal characterization.
Ψ_{JB}: Junction to bottom surface center of PCB thermal characterization.

11. Mechanical Dimensions

11.1. TQFP-176 E-PAD Package



11.2. Mechanical Dimensions Notes

Symbol	Dimension in mm			Dimension in inch		
	Min	Nom	Max	Min	Nom	Max
A	1.00	1.10	1.20	0.039	0.043	0.047
A_1	0.05	0.10	0.13	0.002	0.004	0.005
A_2	0.95	1.00	1.05	0.037	0.039	0.041
b	0.13	0.18	0.23	0.005	0.007	0.009
D/ E	22.00BSC			0.866BSC		
D_1/ E_1	20.00BSC			0.787BSC		
D_2/ E_2	17.20BSC			0.677BSC		
D_3/ E_3	5.75	6.00	6.25	0.226	0.236	0.246
e	0.40BSC			0.016BSC		
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		

Note 1: CONTROLLING DIMENSION: MILLIMETER (mm).
Note 2: REFERENCE DOCUMENT: JEDEC MS-26.

12. Ordering Information

Table 51. Ordering Information

Part Number	Package	Status
RTL8214FCI-VC-CG	TQFP-176 EPAD Green Package	Mass Production

Note: See page 5 for package identification information.

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